



# Understanding, measuring, and reducing output noise in DC/DC switching regulators

**Practical tips for output noise reduction**

**Katelyn Wiggernhorn, Applications Engineer, Buck Switching Regulators**

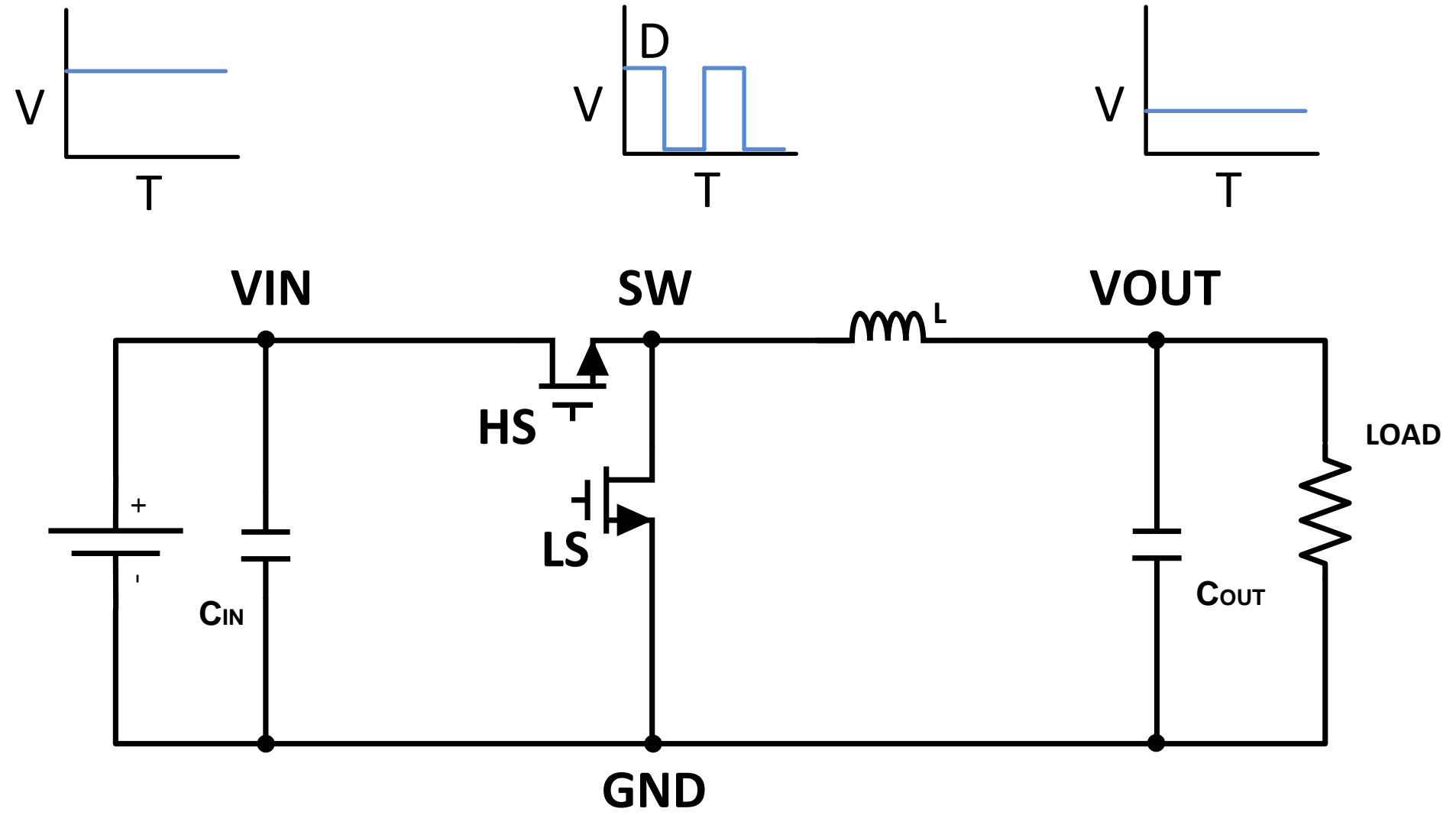
**Robert Blattner, Applications Engineer, Buck Switching Regulators**

# Detailed agenda

- **Understanding the Noise Sources**
  - DC/DC converter operation overview
  - Noise components (high frequency vs low frequency)
  - Relevant parasitic elements in the circuit
- **Measuring Noise**
  - What is “real” vs “fake” noise
  - Examples of measurement techniques (good vs. bad)
- **Reducing Noise (high frequency and low frequency)**
  - Layout techniques and comparison (good vs. bad)
  - Passive component selection and placement
  - Filtering techniques and examples

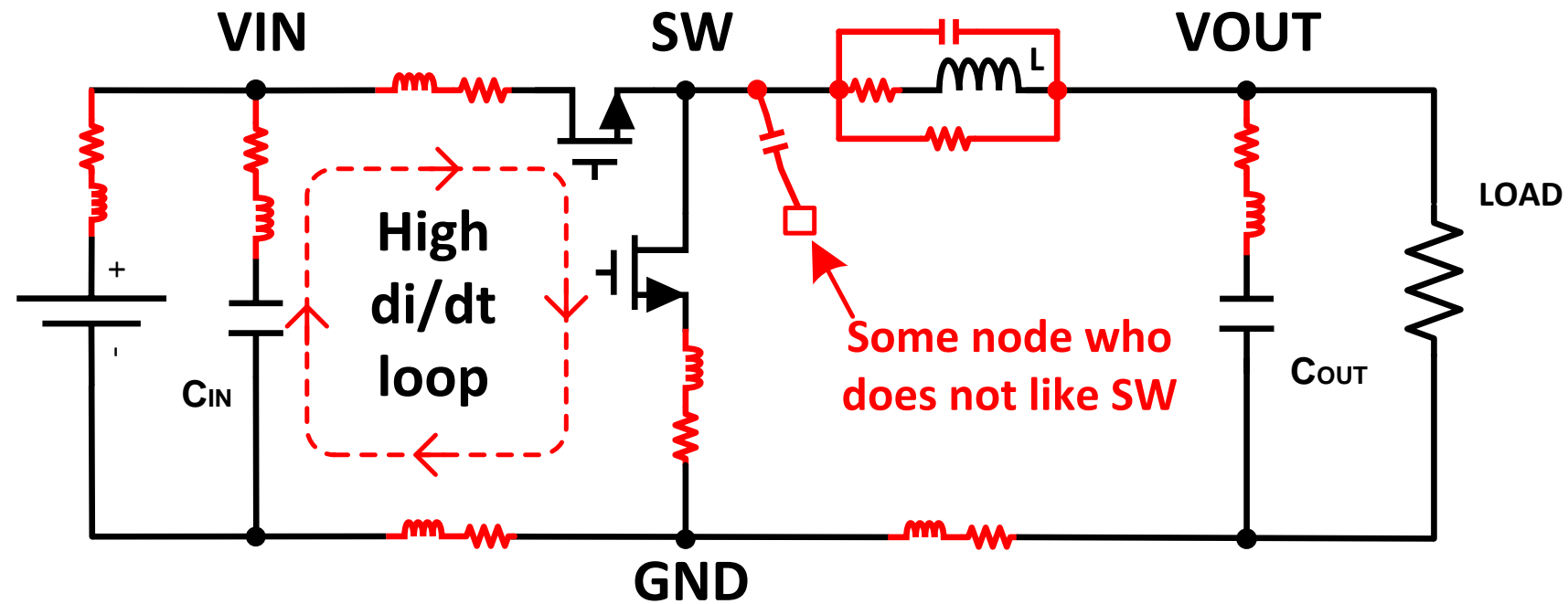
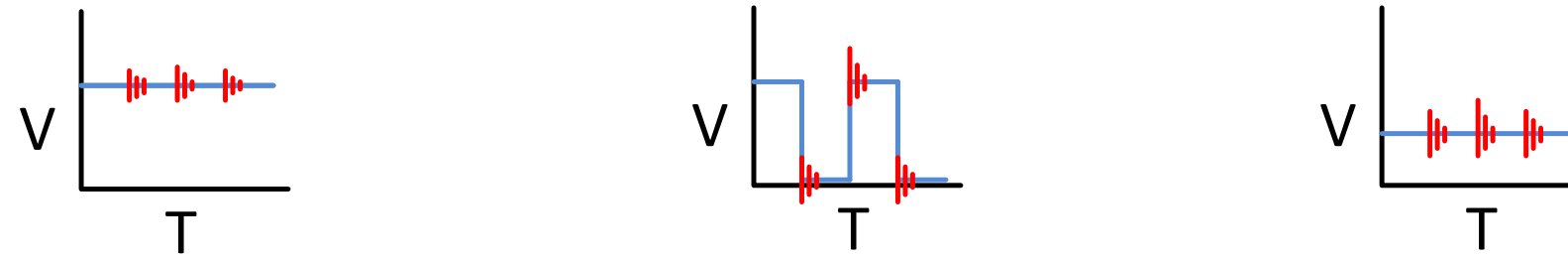
# Understanding the sources of noise

# The buck regulator



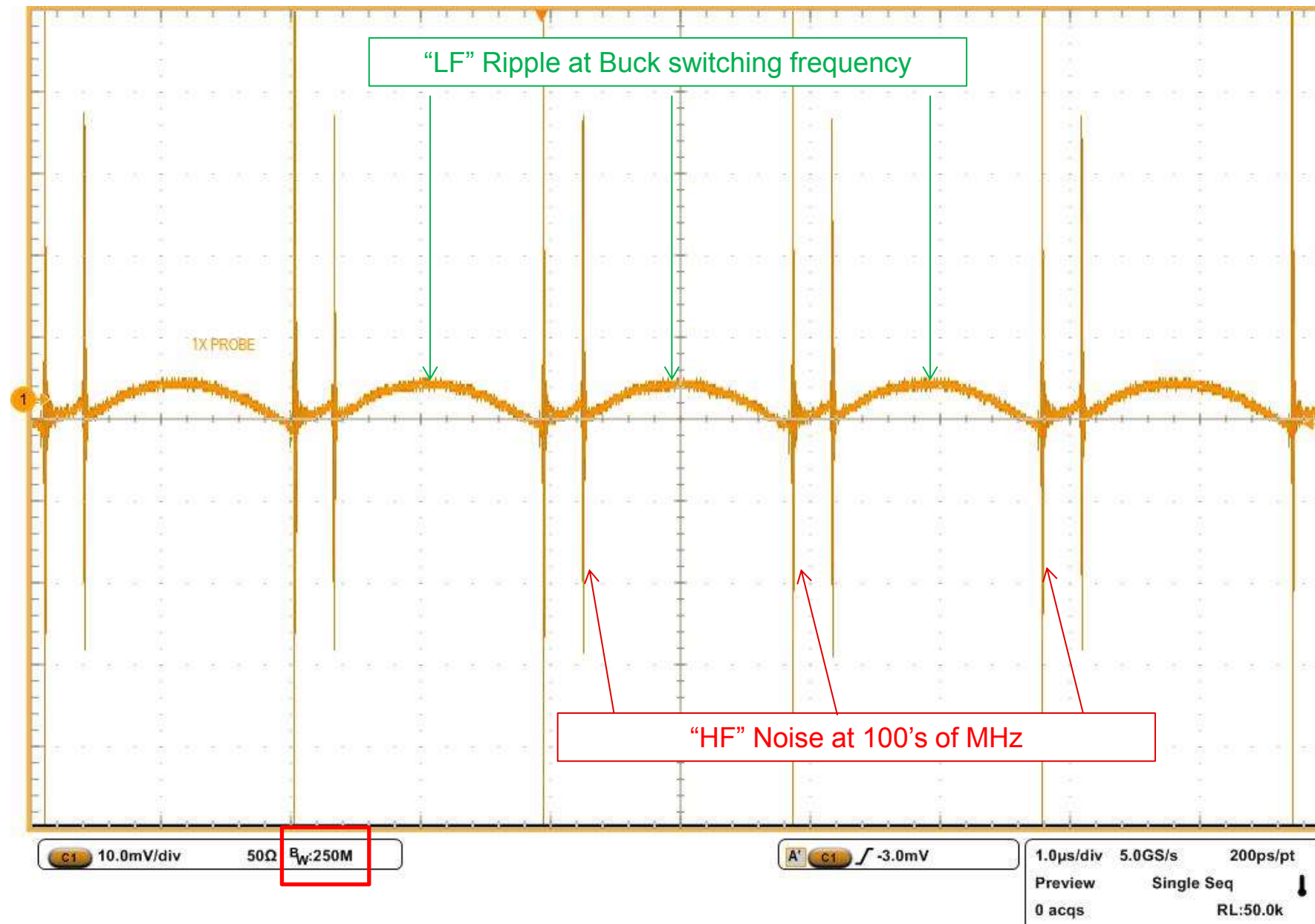
Understanding → Measuring → Reducing Noise

# Less ideal buck regulator



“Free” components in red

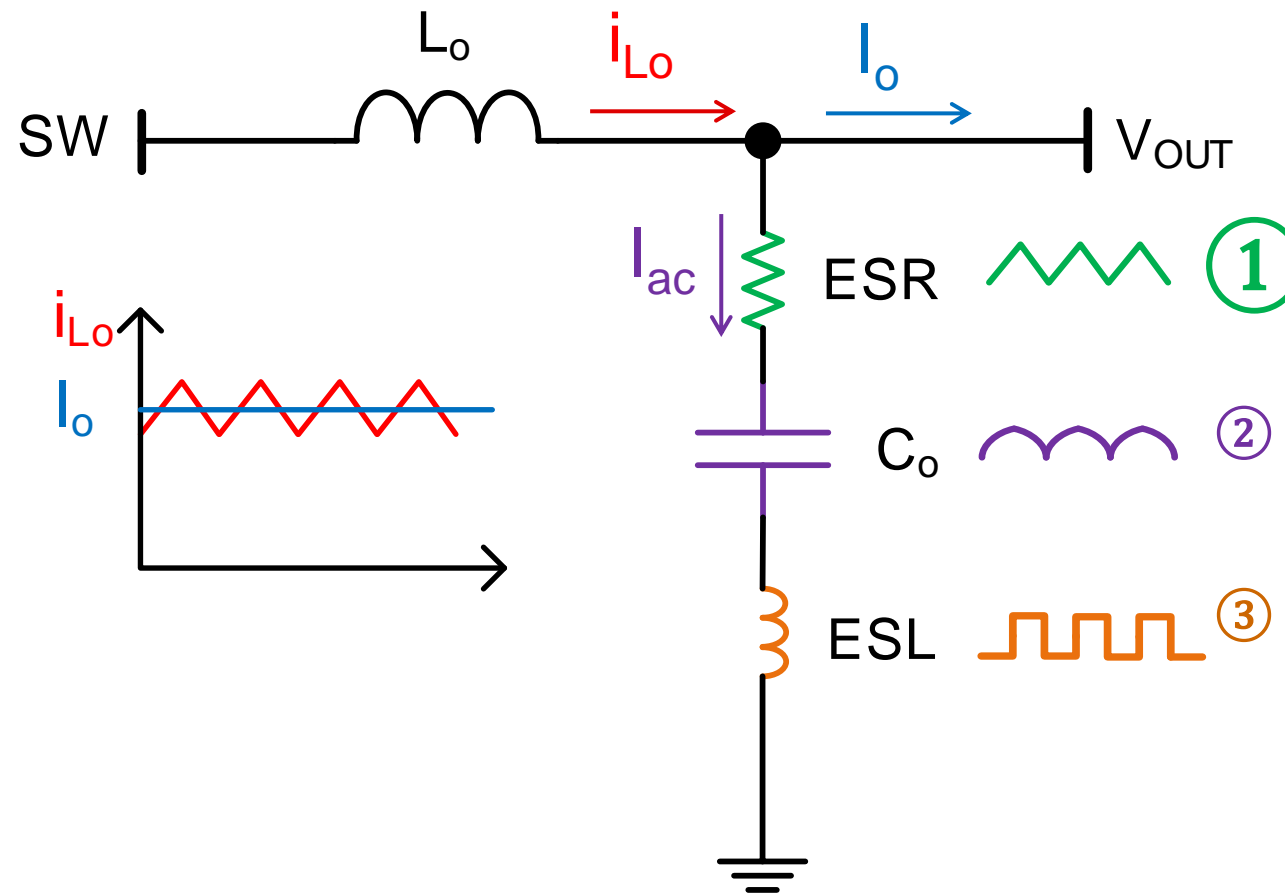
# Output ripple and noise (example)



Understanding → Measuring → Reducing Noise

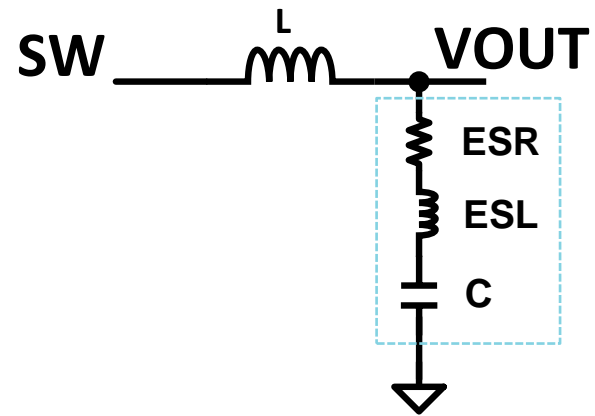
# LF ripple origin

- Result of the inductor ripple current and output capacitor impedance



$$\text{Total LF Ripple} = \textcircled{1} + \textcircled{2} + \textcircled{3}$$

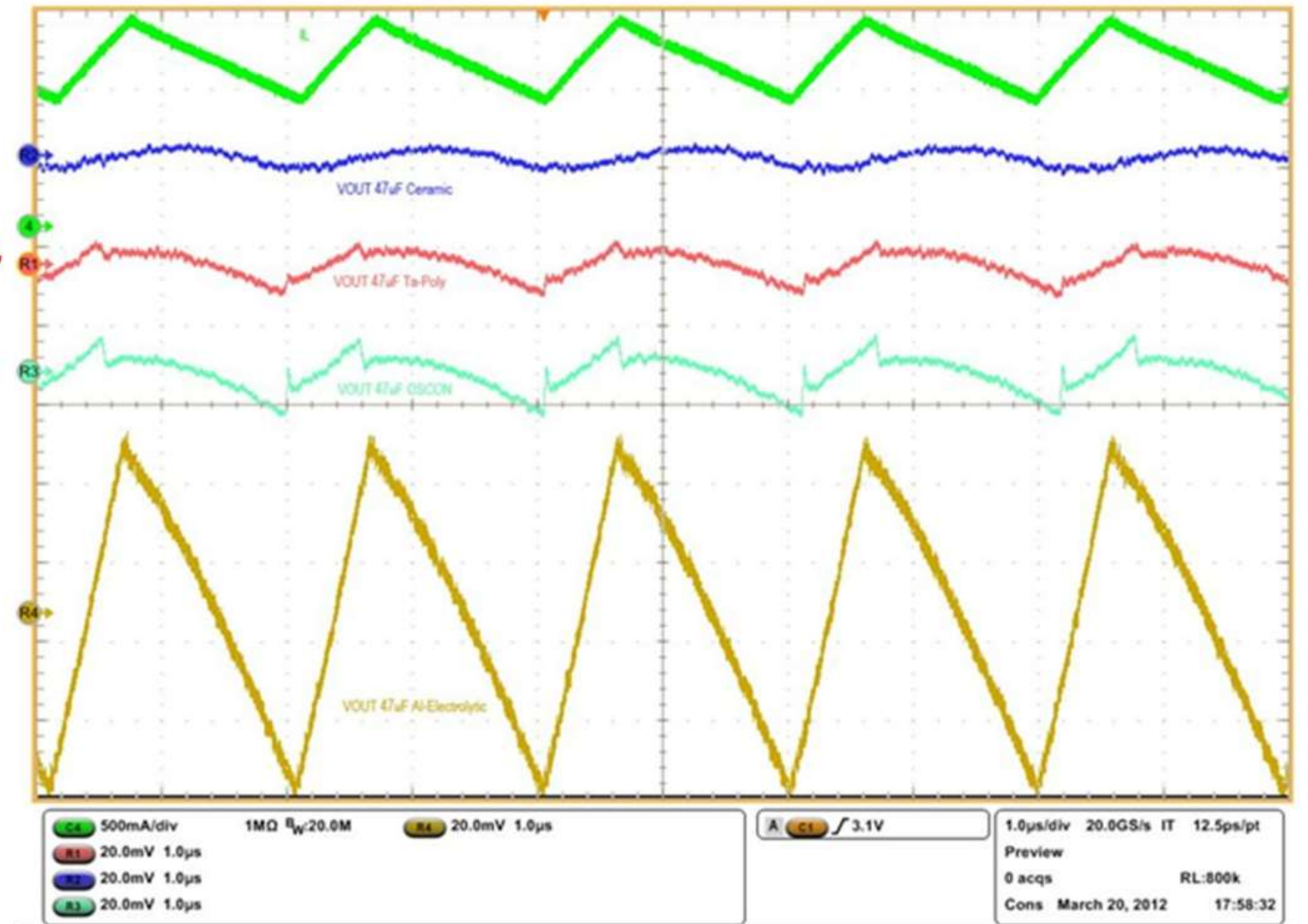
# LF ripple with different capacitor types



“47 $\mu$ F” Capacitor

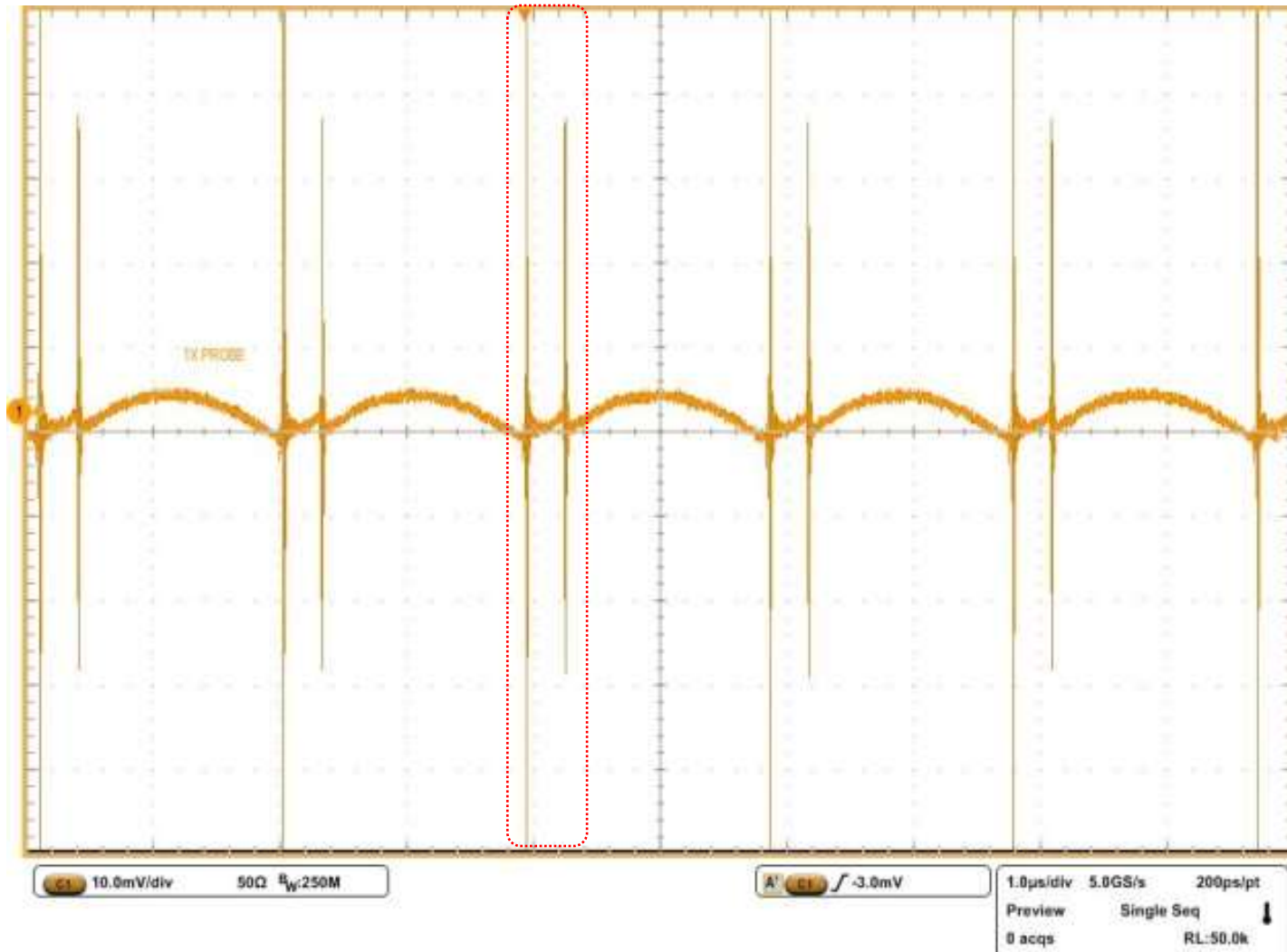
- Inductor ripple current
- VOUT RIPPLE Ceramic cap (C dominated, low ESR low ESL)
- VOUT RIPPLE Tantalum cap (medium ESR, some ESL)
- VOUT RIPPLE OSCON cap (medium ESR, some more ESL)
- VOUT RIPPLE Aluminum Electrolytic cap (ESR dominated)

Each capacitor above is 47 $\mu$ F.  
The difference is the chemistry

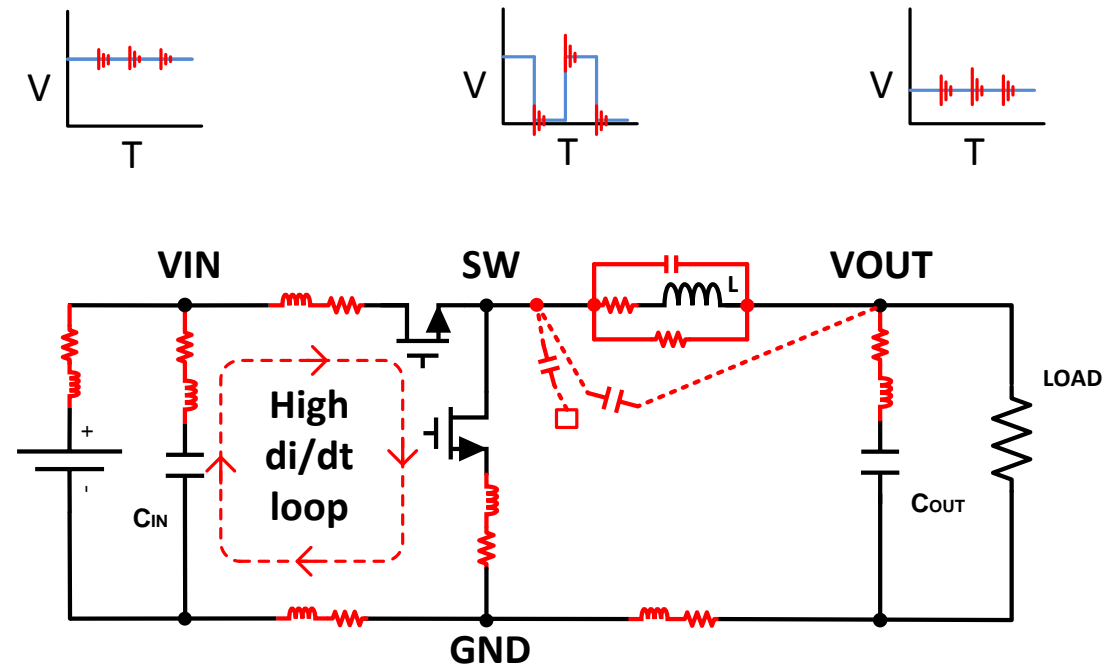




# HF noise origin



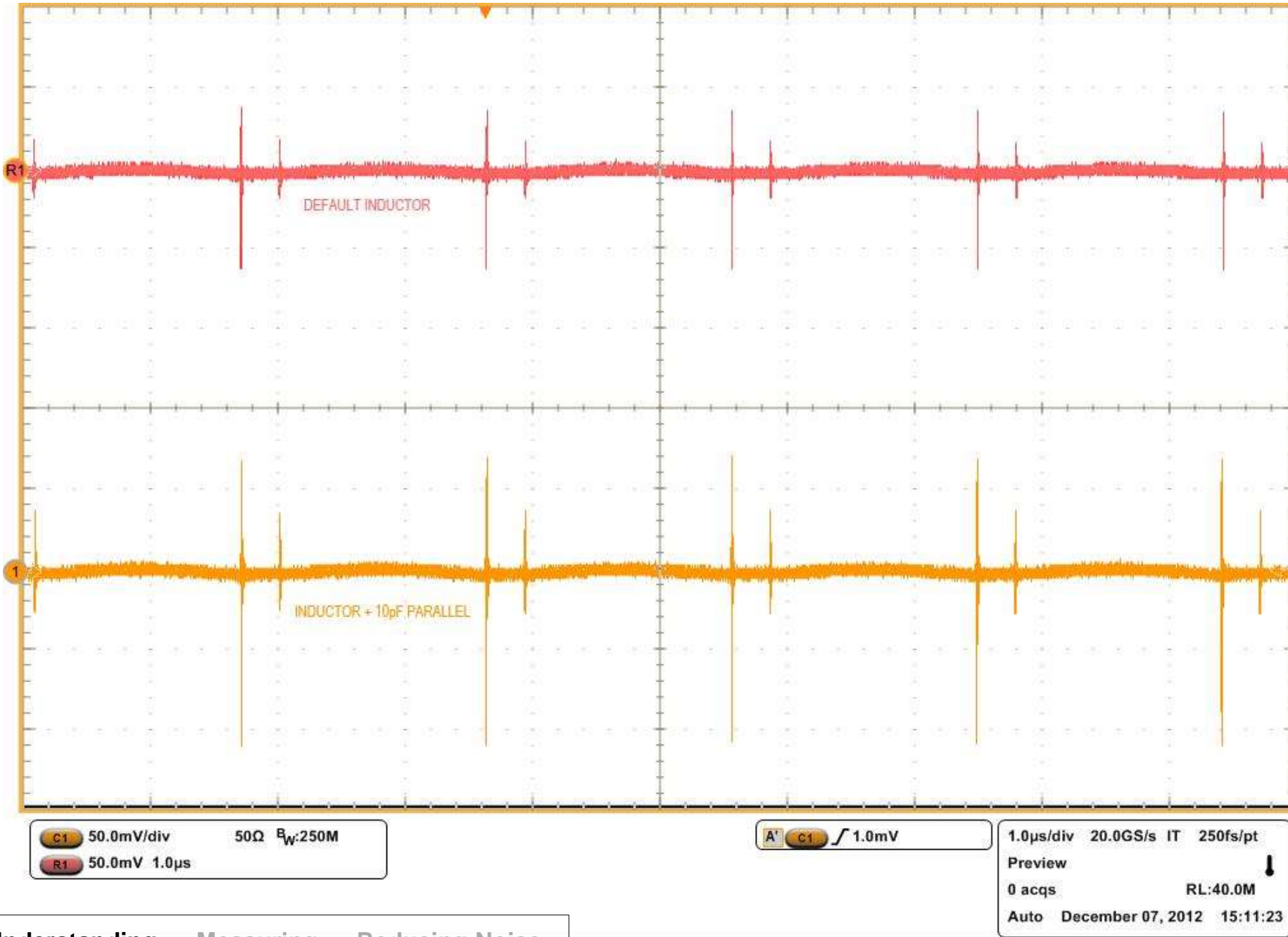
- Who is generating the noise?
  - High  $di/dt$  current loop and any inductance in its path
  - Noise appears on the SW node as ringing at each edge



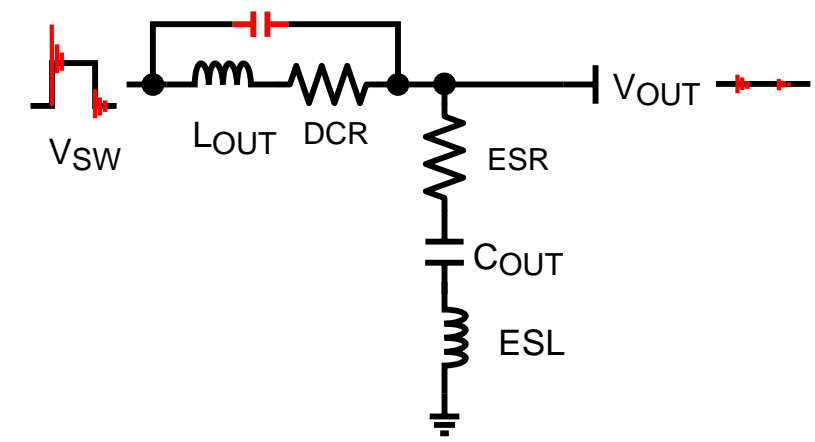
- How is the ringing coupled to the output?
  - Parasitic capacitance
    - Across the inductor (could be a few 10's of pF)
    - Between overlapping copper areas on the PCB

“Free” components in red

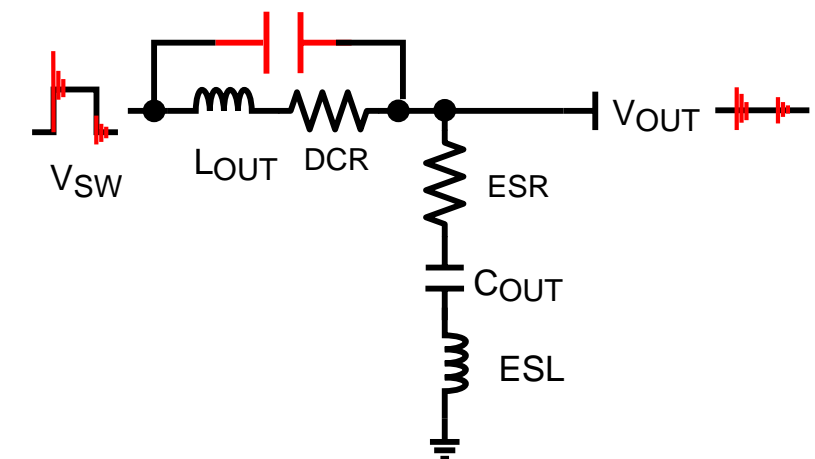
# HF noise vs inductor parasitic capacitance



Inductor A



Inductor B



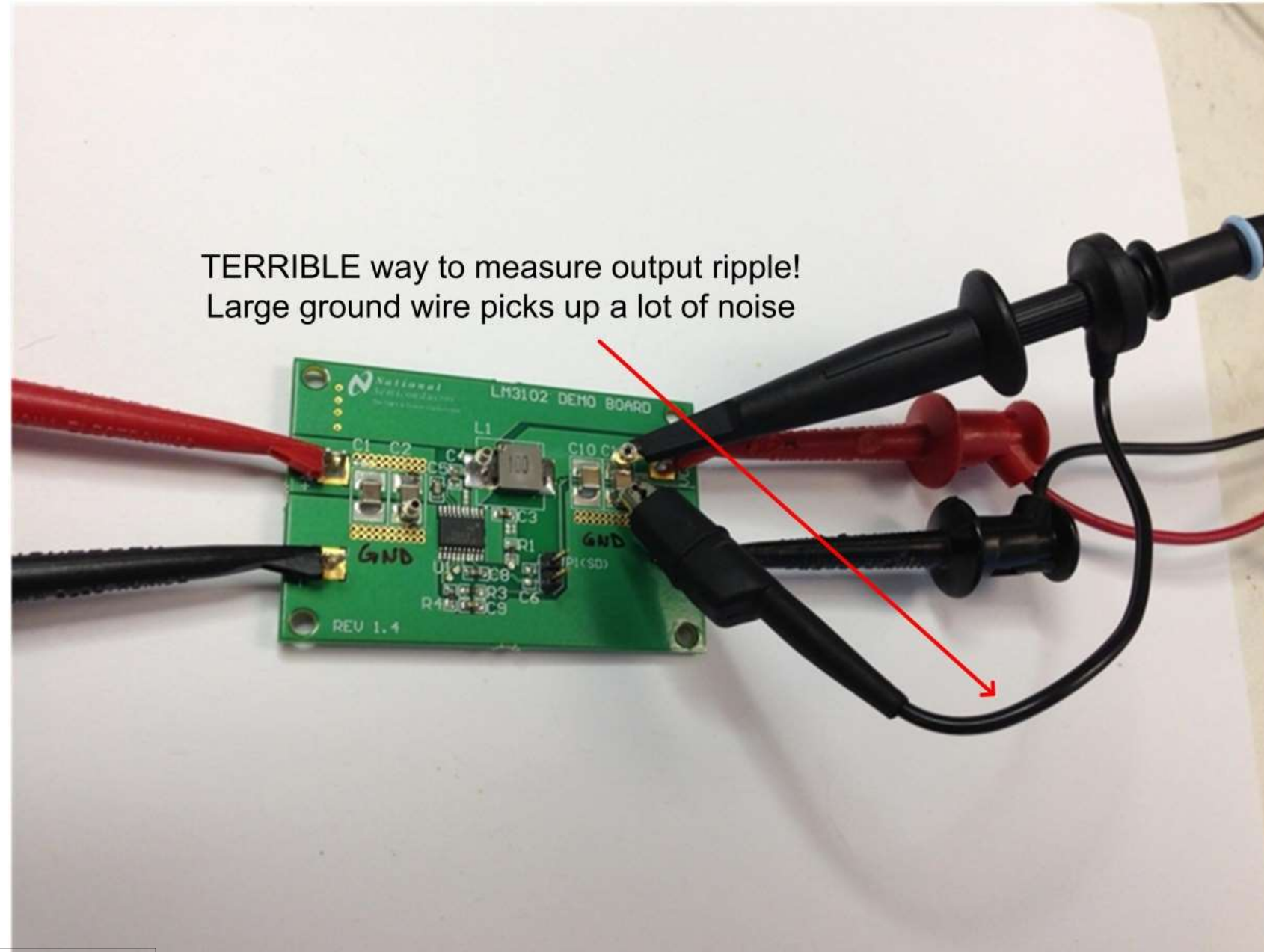
Understanding → Measuring → Reducing Noise

# Measuring noise

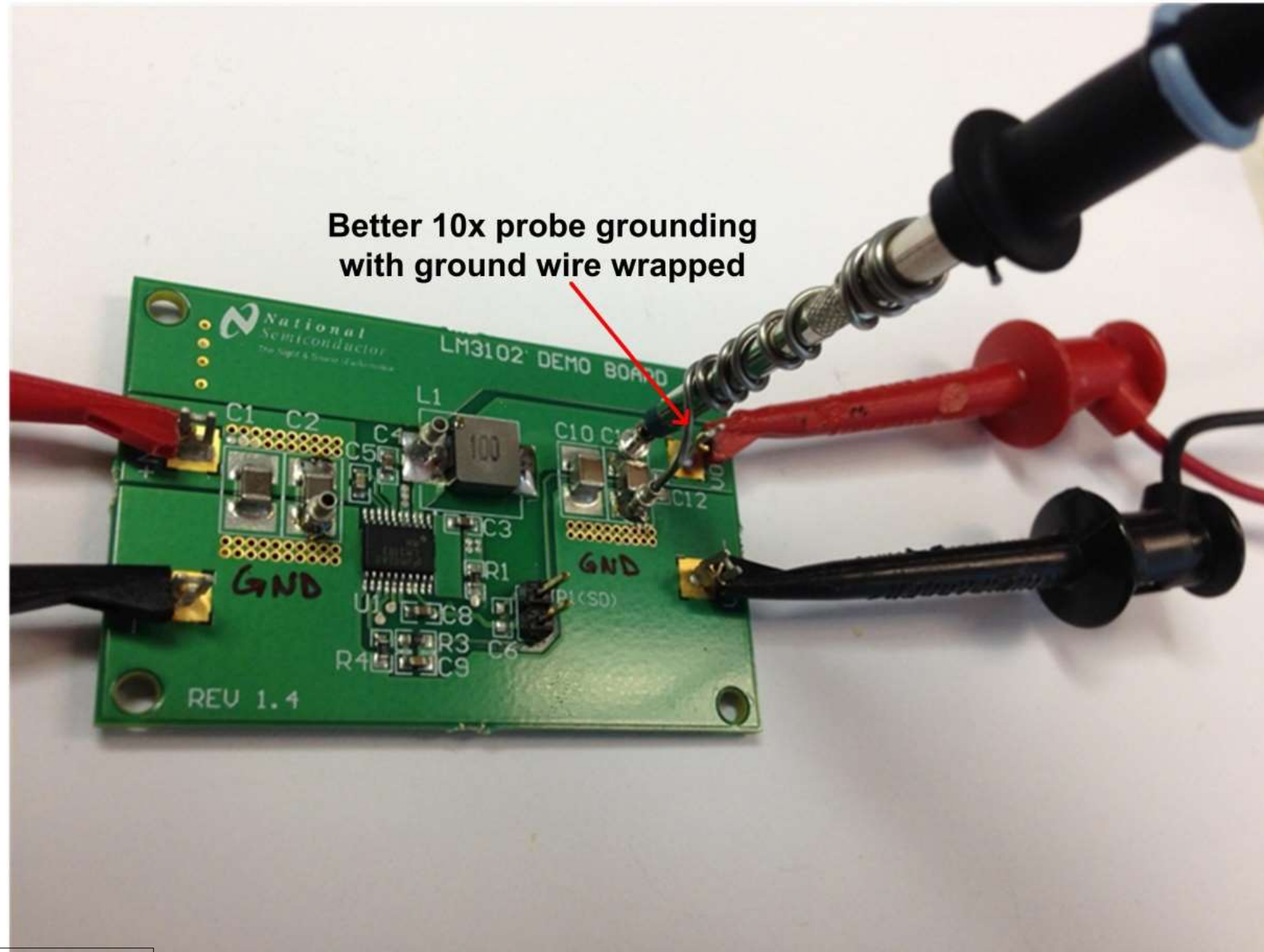
# Measuring noise

- Before we explore ways/tools for reducing the output noise, let's make sure we are measuring it properly.
- Improper measurement techniques can result in exaggerated output noise.
- Exaggerated output noise measurements can result in overly conservative “methods” for fixing it.
- It is important to know the “real” amount of noise before we start reducing it.

# BAD Measurement (example)

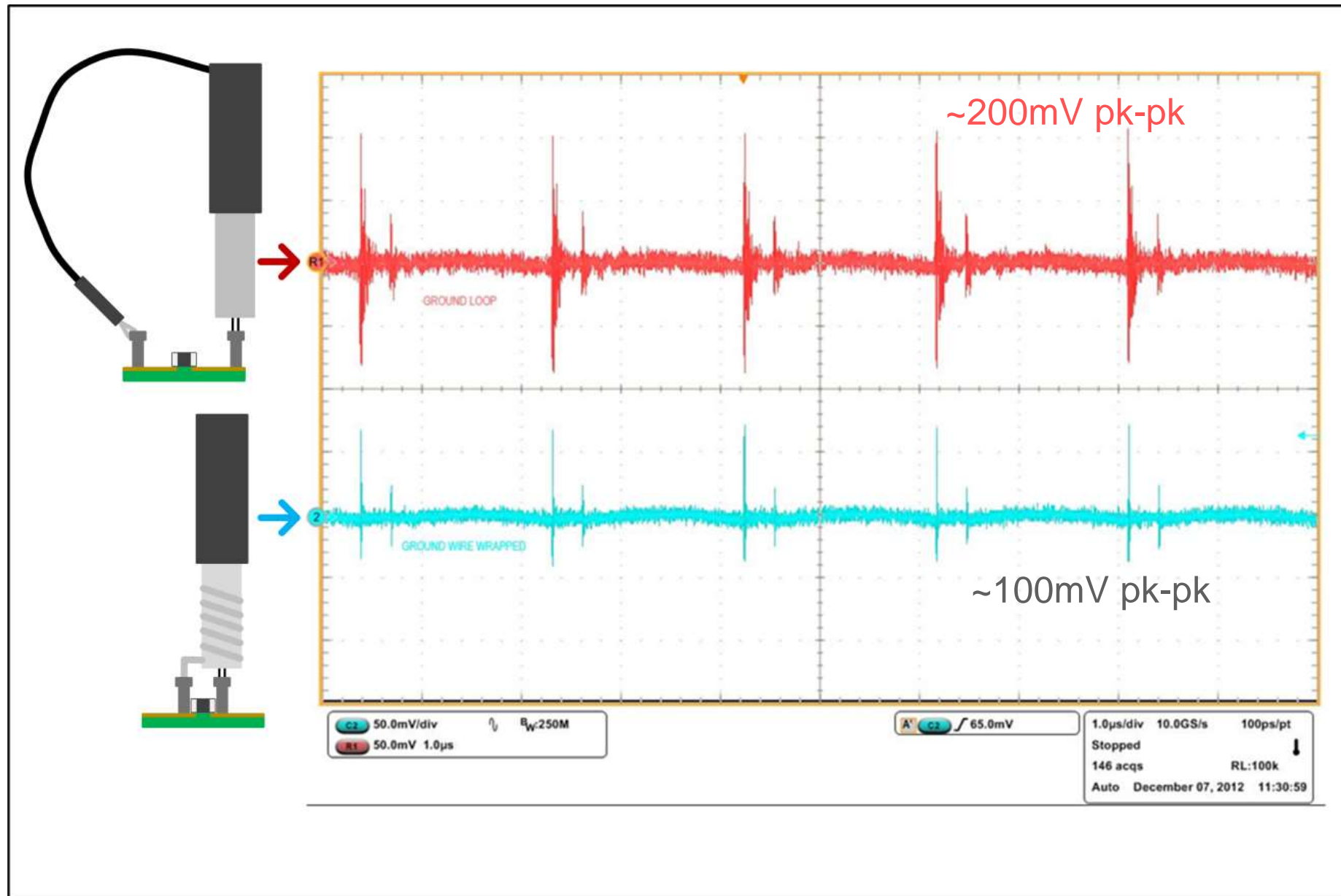


# Improved measurement (example)



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# Comparison

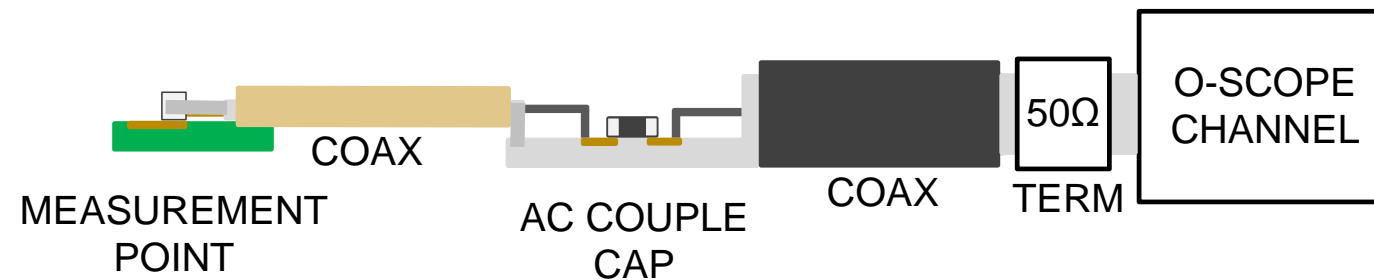
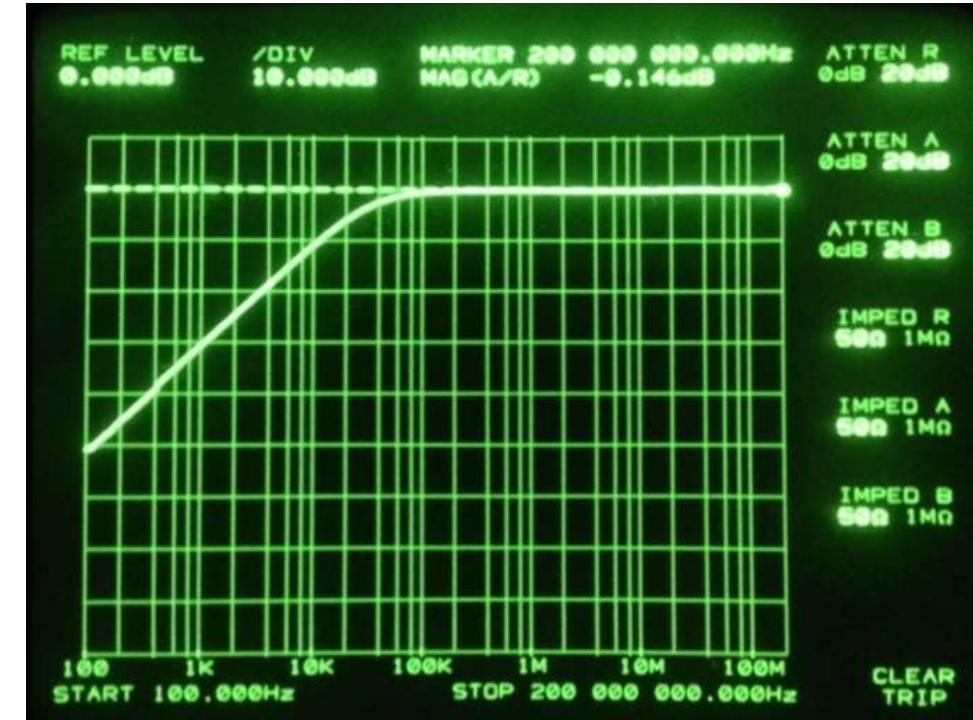


~2x difference in measured noise!

The circuit is exactly the same.  
The difference is the measurement technique.

# Making a 1x probe (example)

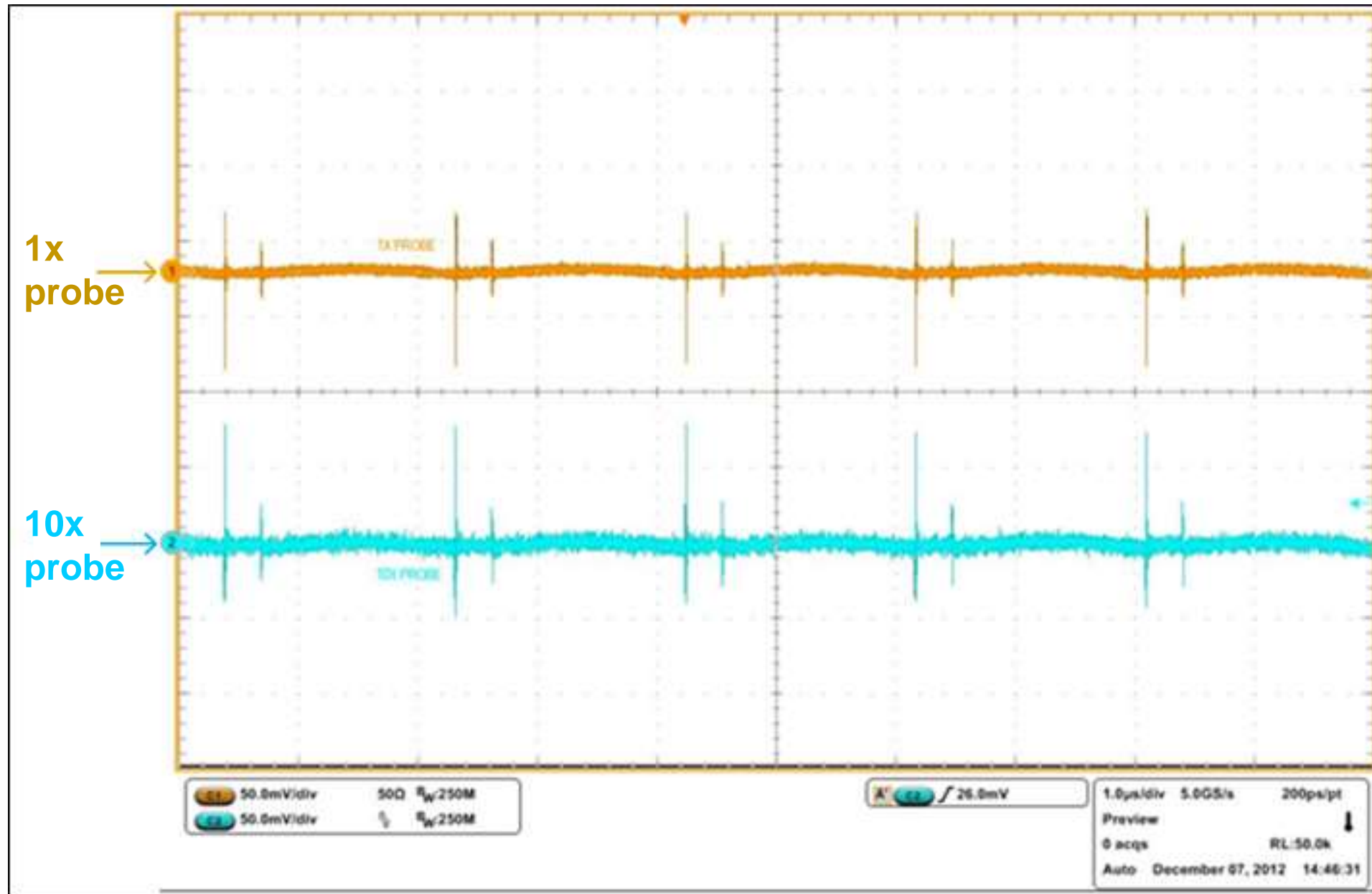
- Short coax cable soldered to the output
- 0.1 $\mu$ F coupling capacitor
- 50 $\Omega$  termination



- Probe frequency response
- High pass filter with cutoff frequency at 31.8kHz. OK for most modern switchers with loaded output.
- Probe OK for 250MHz scope BW



# Advantage of 1x probe



Cleaner reading  
Can zoom to 1mV/div for sub 1mV measurements

Fuzzy due to the scope vertical sensitivity limitations of a 10x probe. Cannot zoom below 10mV/div

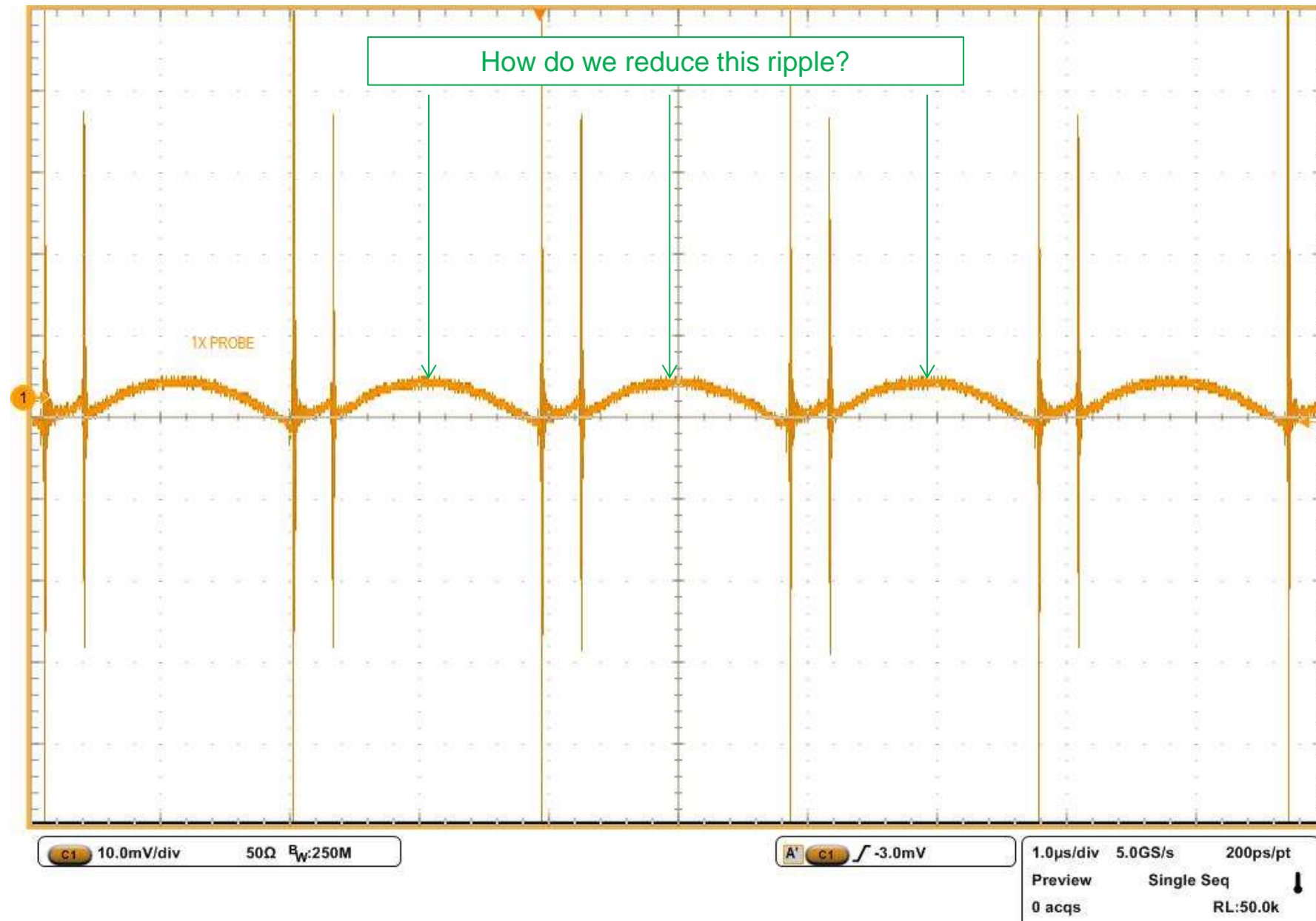
# Reducing noise

# Reducing noise - toolbox

- LF Ripple
  - Inductor vs Switching Frequency
  - Output capacitor
  - Post filtering
- HF Noise
  - Component placement
  - Component selection (with attention to packaging parasitics)
  - PCB routing and stack-up
  - Filtering
    - Input filters (conducted EMI)
    - Output filters (small HF capacitors)

# LF ripple reduction

# LF ripple reduction



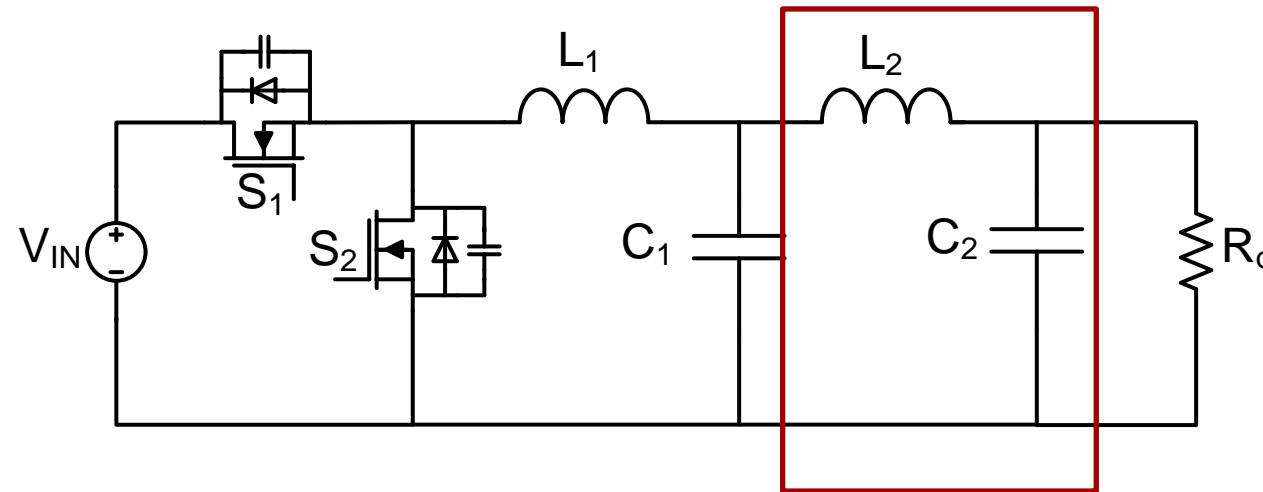
Understanding → Measuring → Reducing Noise

# LF ripple – switching frequency and inductance

- We understand that the LF ripple is a function of the inductor ripple current and the output capacitor(s) impedance.
- We can:
  - **Lower the ripple current**
    - For the same inductor, increase the switching frequency
      - Tradeoff: increased switching losses
    - For the same switching frequency, increase the inductance
      - Tradeoff: increased solution size
  - **Lower the capacitor impedance**
    - Use low ESR and low ESL capacitors
      - Tradeoff: perhaps cost
    - Use multiple capacitors in parallel
      - Tradeoff: cost, board space

# LF ripple – second stage filter

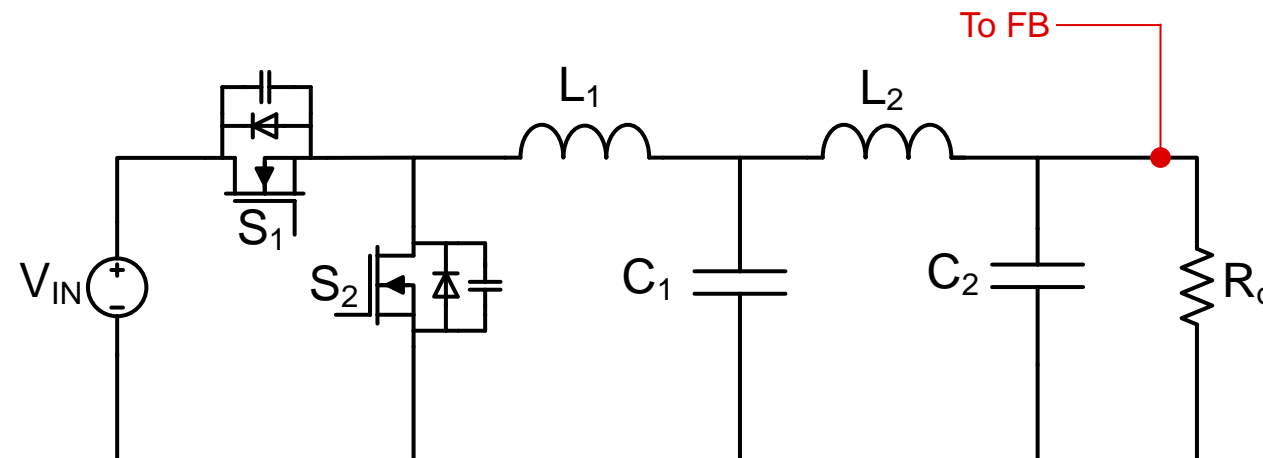
- Certain applications, such as test and measurement, are sensitive to the voltage ripple and routinely require very low output voltage ripple, such as 0.1%.
- To attain this level of attenuation it is required to add another pair of L and C to the output of a buck regulator as shown in the image below.



Buck with a second-stage LC filter

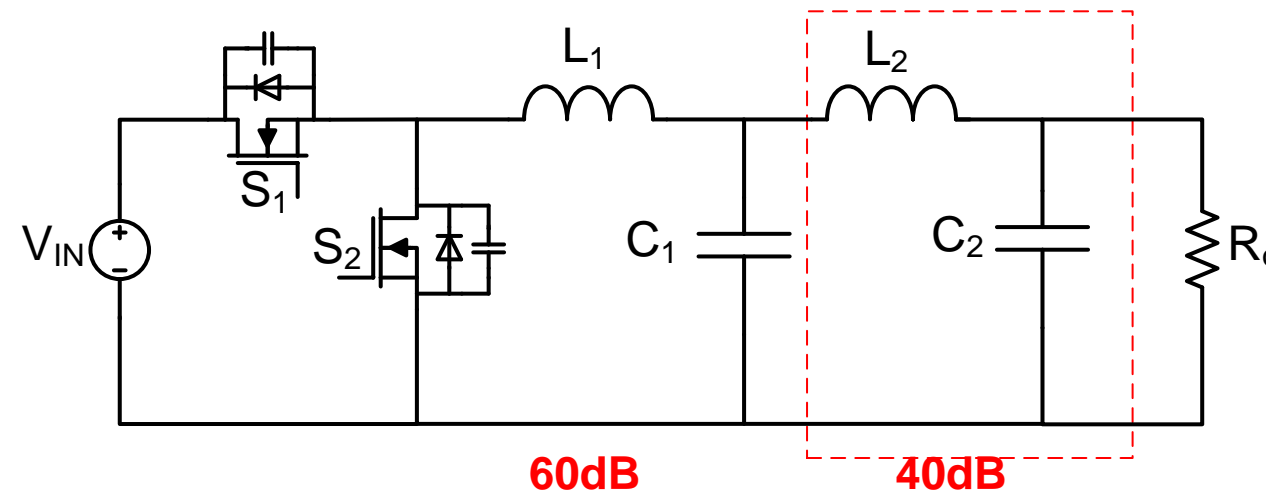
# Second stage filter and output sense

- Common concern is how to position the 2<sup>nd</sup> stage filter – before or after the feedback (VO<sub>UT</sub>) sense point.
- **Assumption:** The second stage filter should be placed after the VO<sub>UT</sub> sensing point to avoid instabilities.
- **Reality:** Regardless of the connection the filter still interacts with the original output capacitance and there is resonance created.
- Connecting the filter before the VO<sub>UT</sub> sense:
  - allows us to account for it in the stability review
  - there is no load regulation penalty – resistive drop is compensated by the sense.





# Second stage filter – component calculations

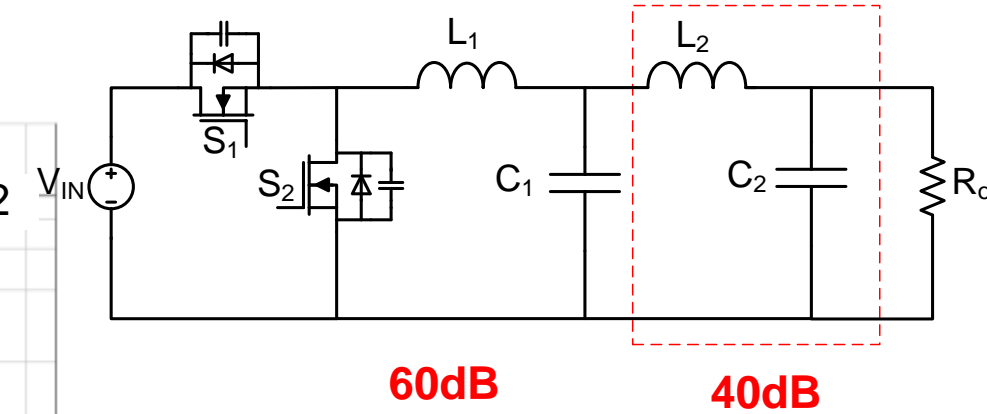
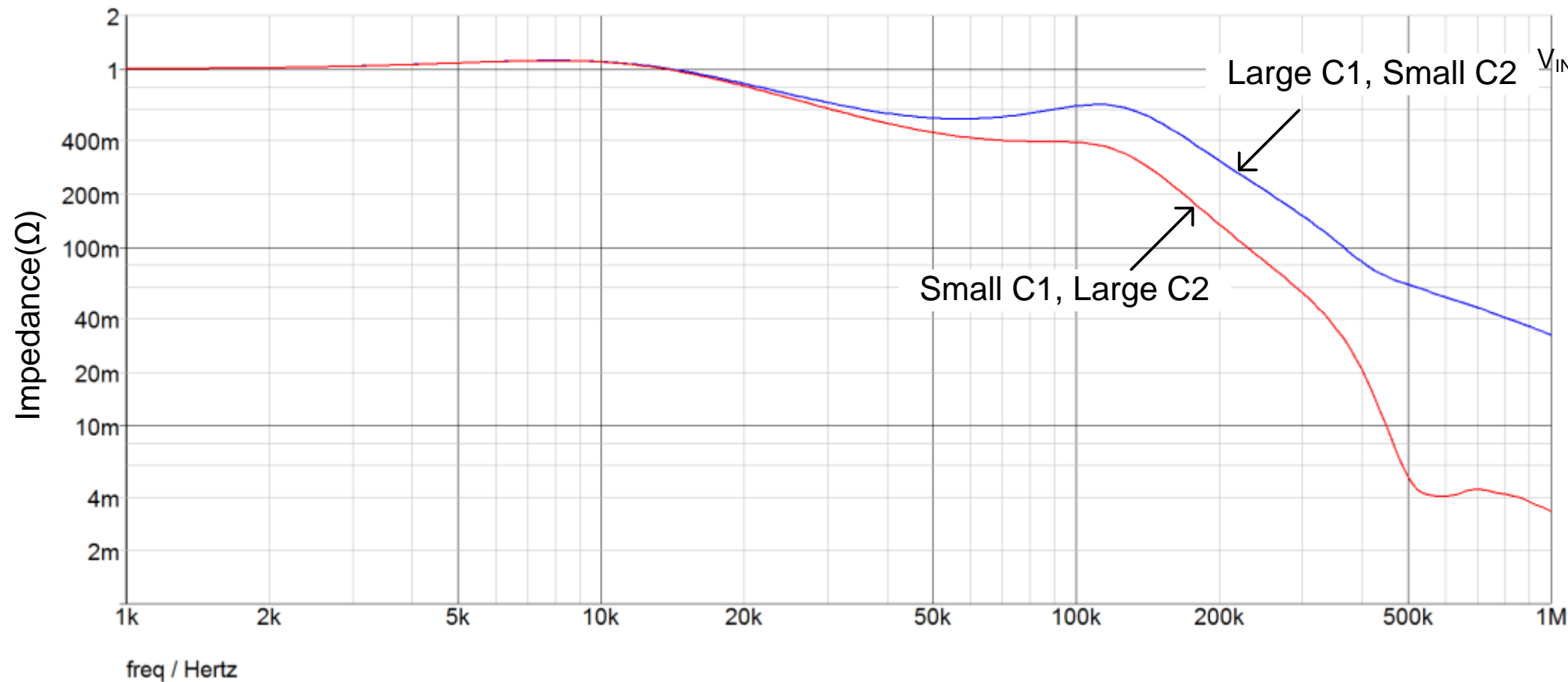


Buck with a second-stage LC filter

- Improper design of the second stage filter could make the converter unstable.
- Two objectives
  1. Attenuation
  2. Loop stability

# Second stage filter – component calculations

- To ensure low impedance and to make sure the filter doesn't affect the loop substantially, the ratio of first stage (C1) to second stage capacitance (C2) is set to 1:10
- The value of the secondary inductor is then chosen for the remainder 40dB attenuation.

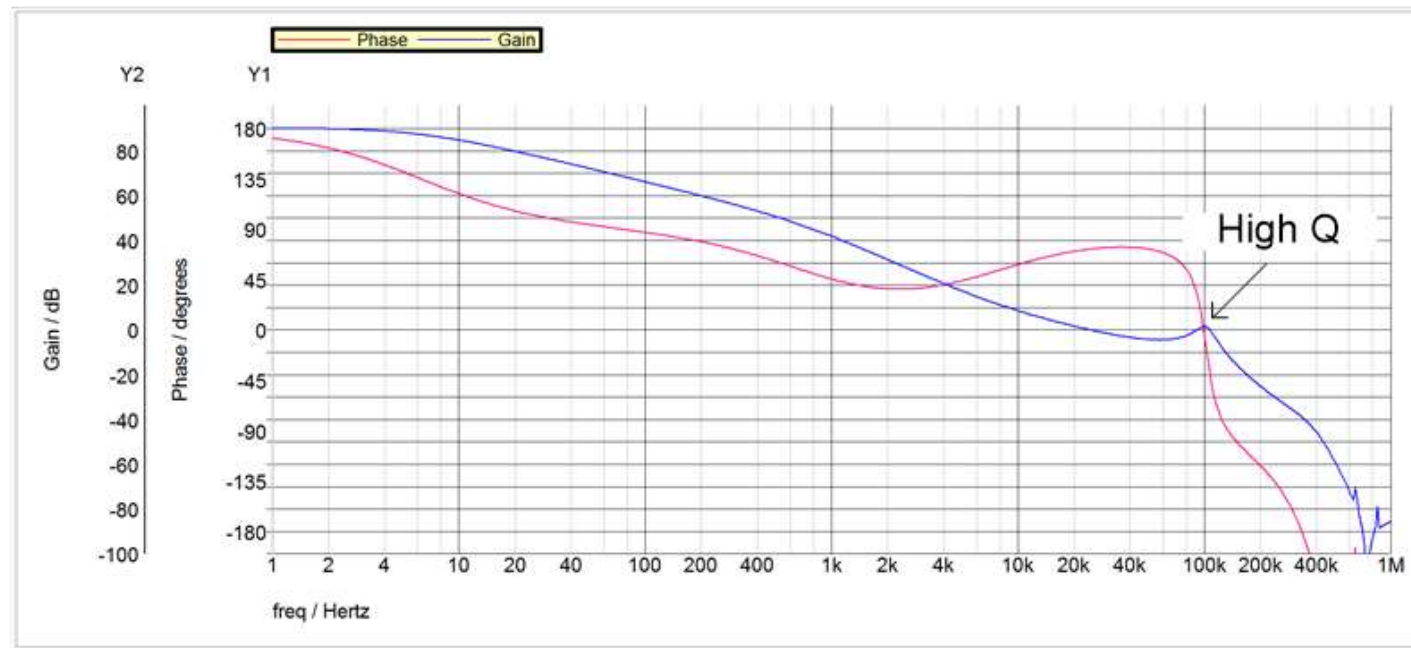


## Steps:

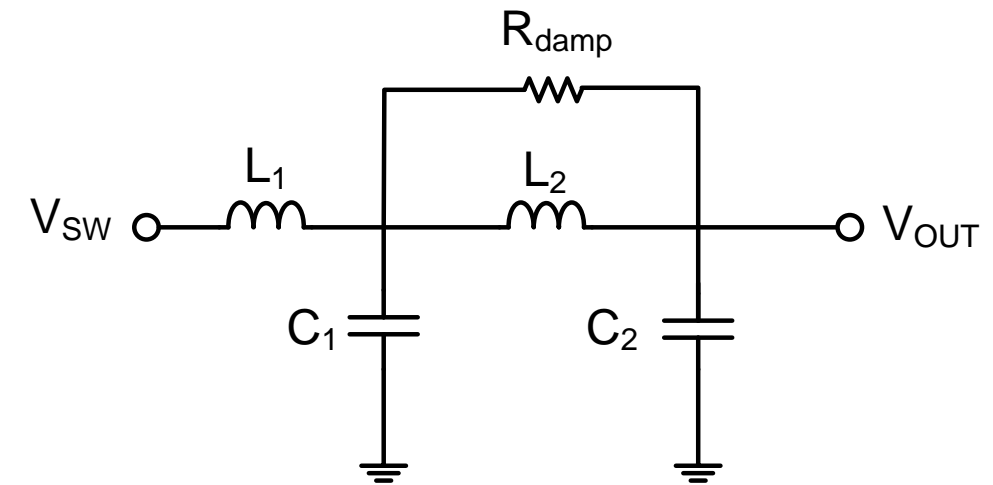
1. Calculate  $L_1$  (usually based on ripple current)
2. Calculate  $C_1$  based on the 1<sup>st</sup> stage attenuation
3. Set  $C_2$  to be 10 x  $C_1$
4. Calculate  $L_2$  based on the 2<sup>nd</sup> stage attenuation

# Second stage filter – Q and damping

- There may be a need to add a damping resistor in parallel with the inductor



High Q results in low phase margin



Placing the resistor parallel to the inductor damps the Q

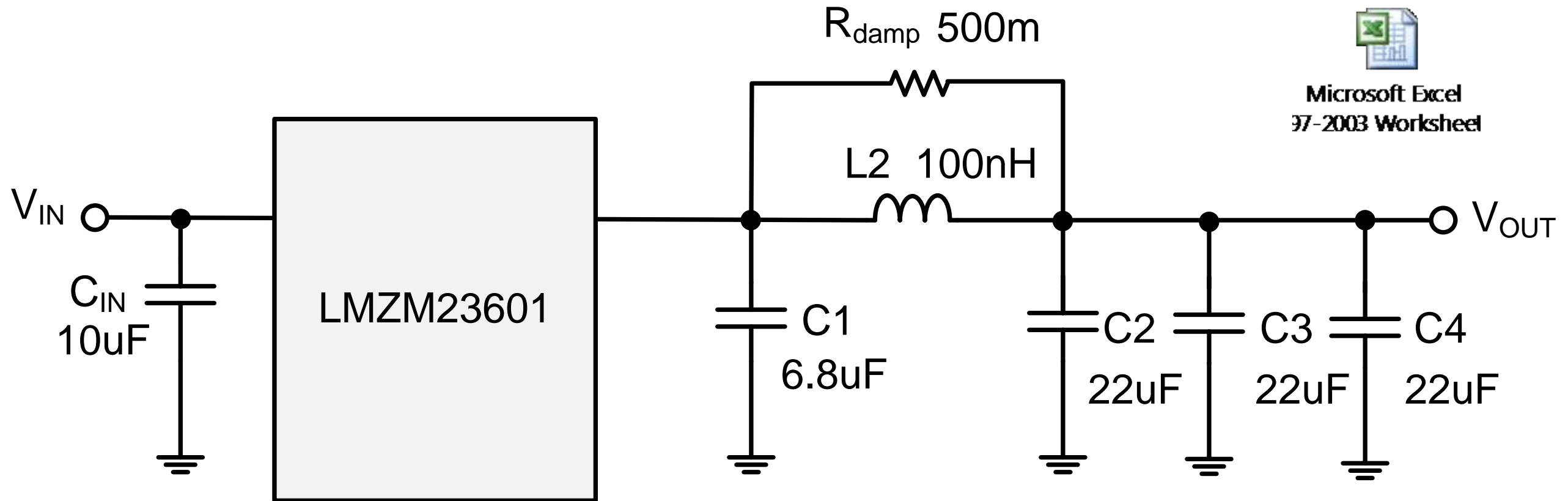
# Second stage filter – choosing $R_{damp}$ and $L2$

- LMZM23601 with second stage filter.

Filter Calculator with Equations



Microsoft Excel  
97-2003 Worksheet

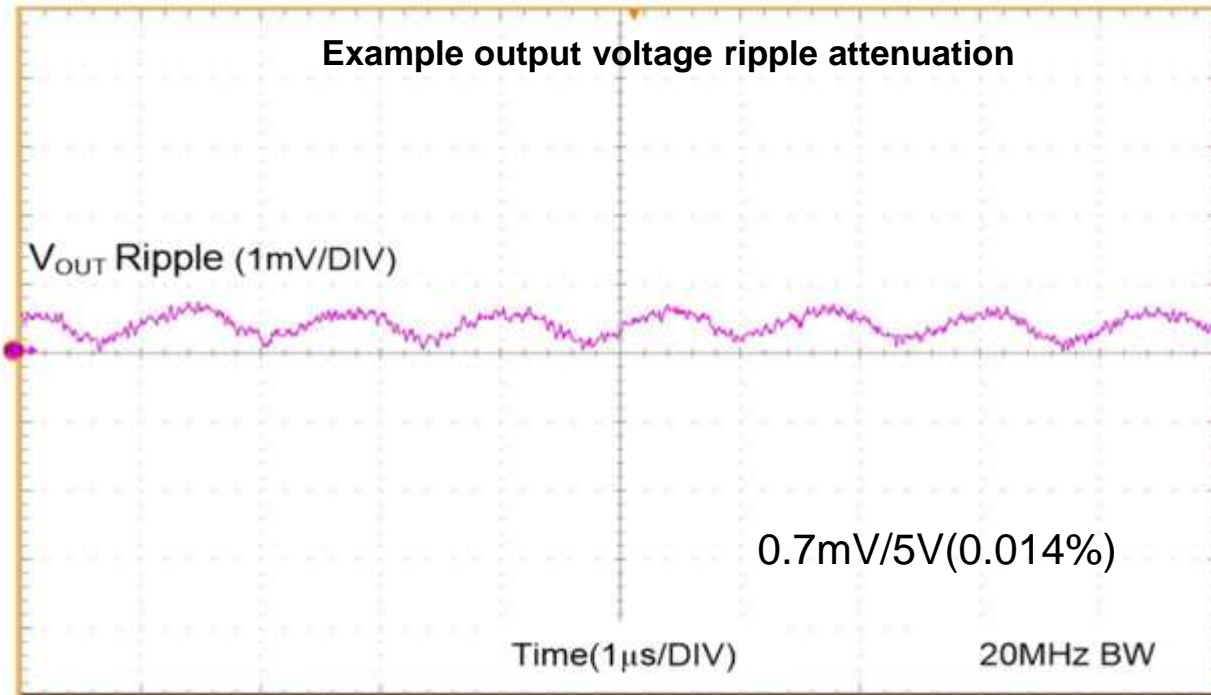


LMZM23601 with a second-stage filter

# Second stage filter - results

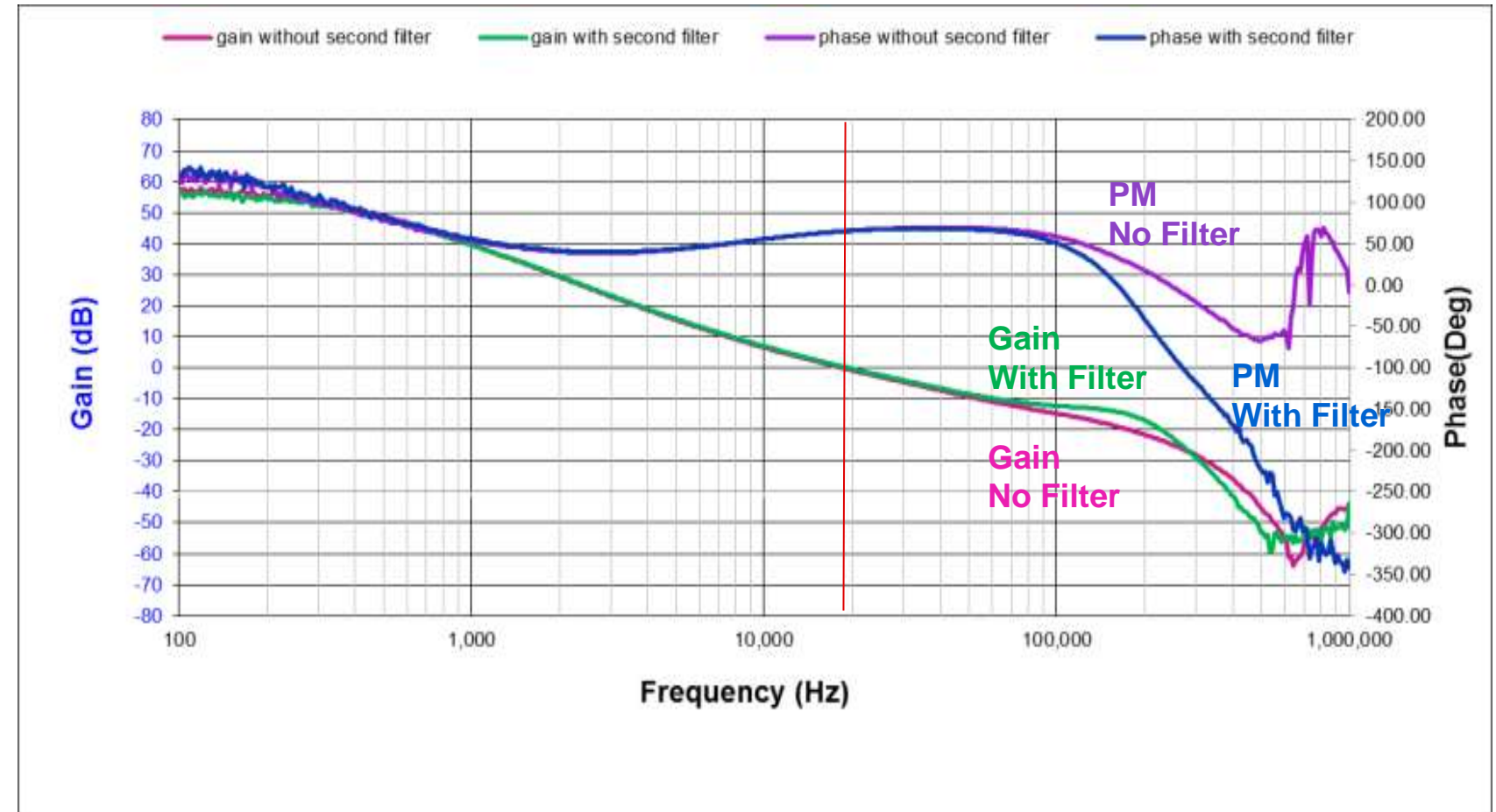
- LMZM23601 with second stage filter.

## Attenuation



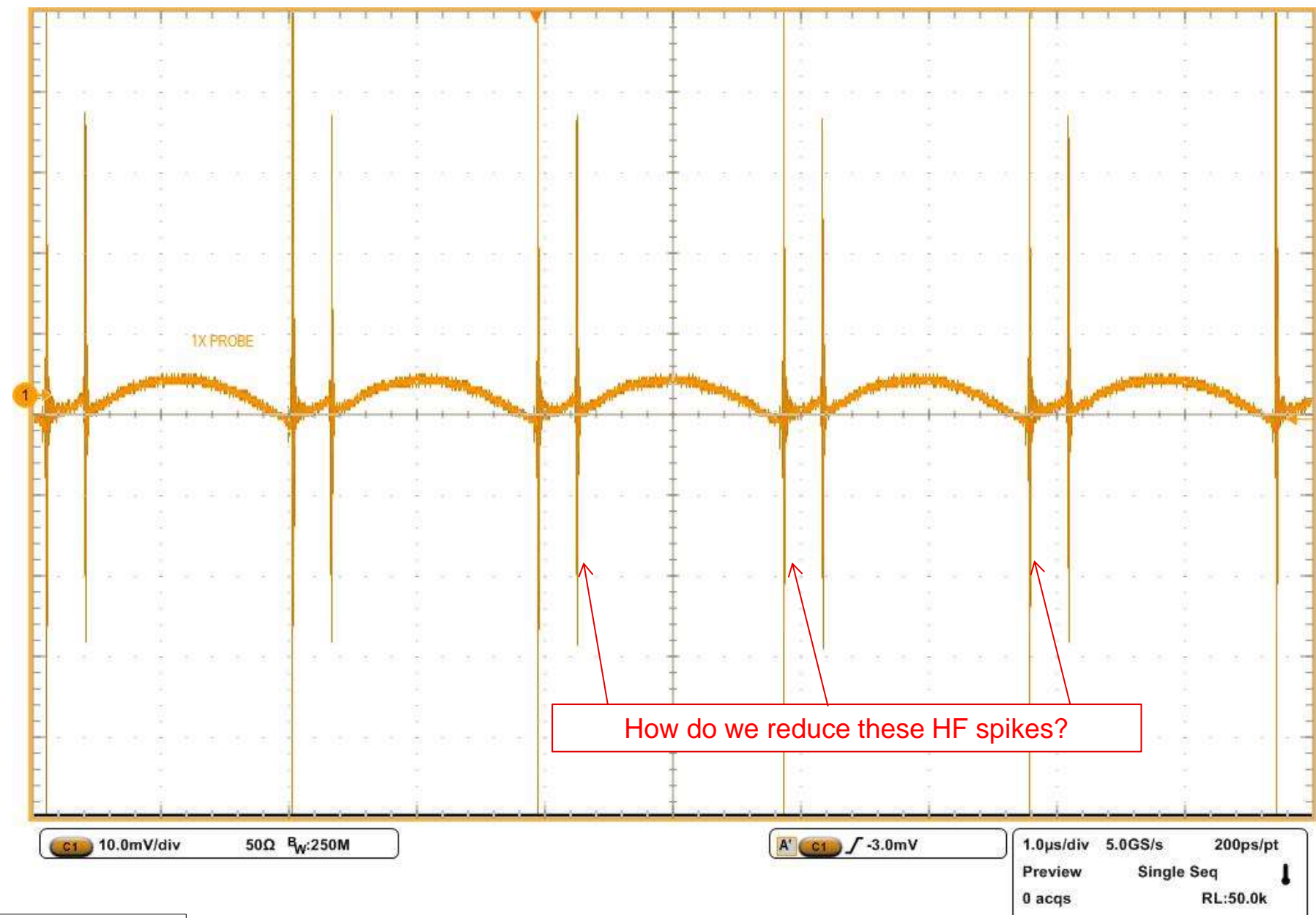
## Stability

Bode plot with and without the second-stage filter



# HF noise reduction

# HF noise reduction



How do we reduce these HF spikes?

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# HF noise reduction – component placement

- First step is to optimize (minimize) the area of the **high di/dt loop**.
- For Buck, the high di/dt loop is formed by the input capacitor and the power MOSFETs (switches).
  - Input capacitor as close as possible to IC = Smaller loop area
  - Smaller loop area = Lower ringing on SW node
  - Lower ringing on SW node = Lower output noise
- So first step = optimize input capacitor placement for Buck

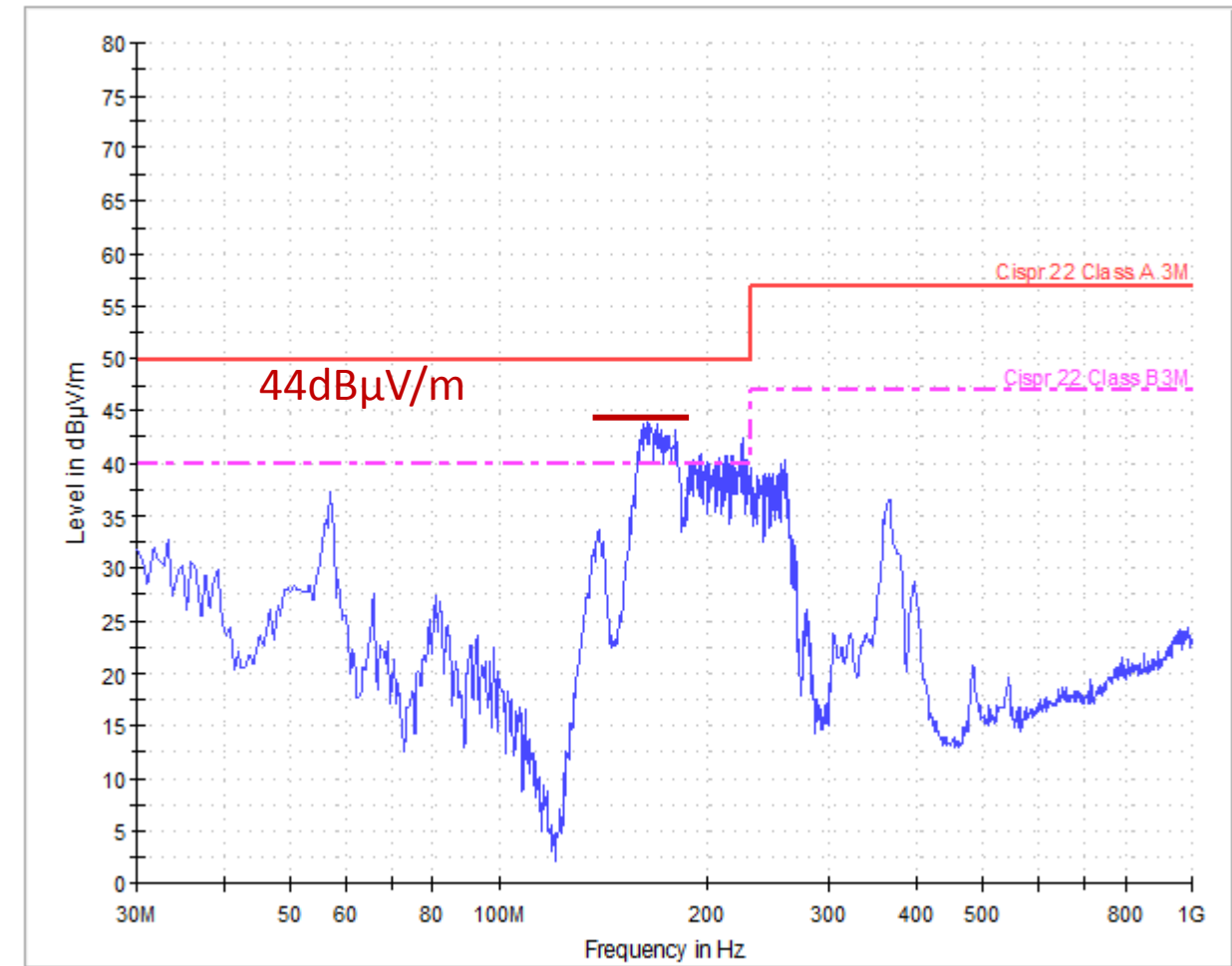
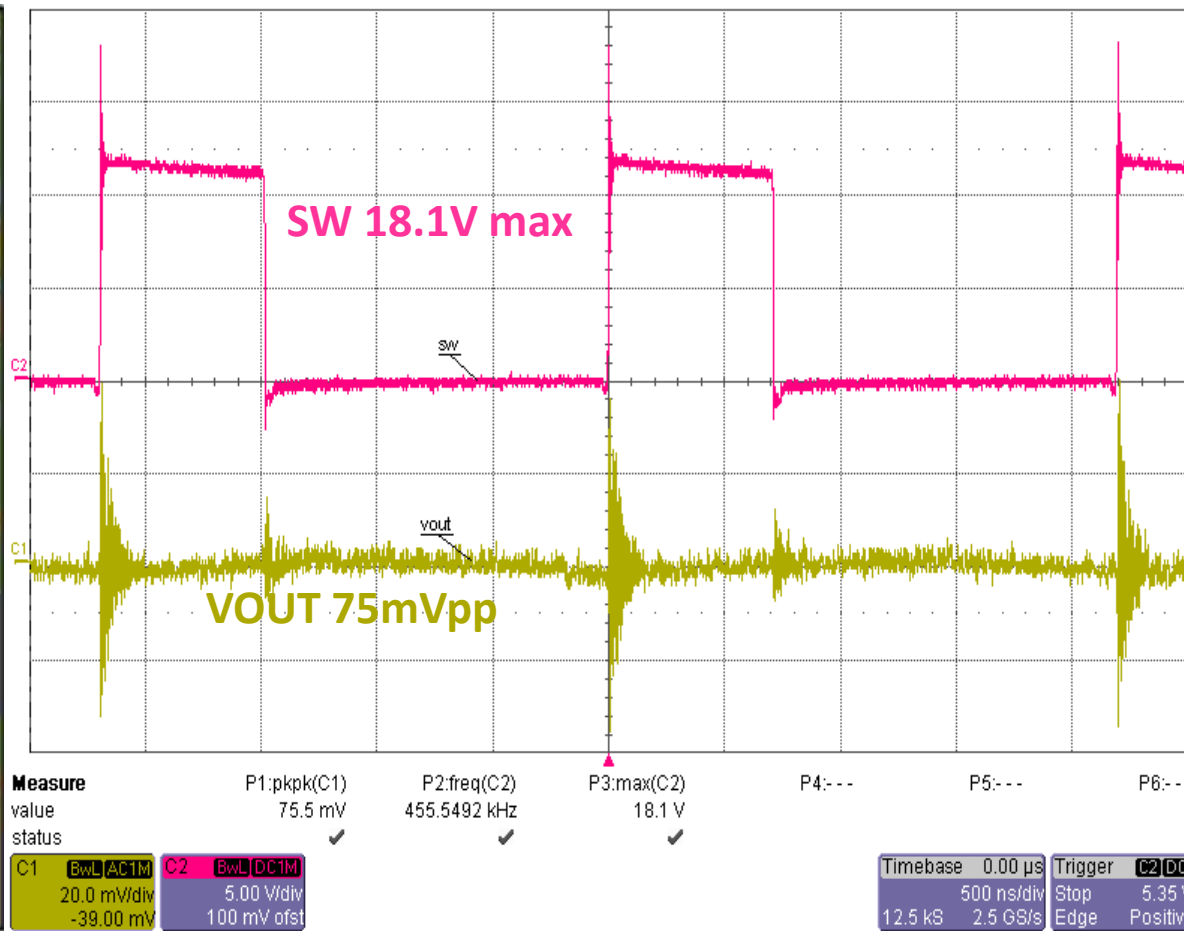
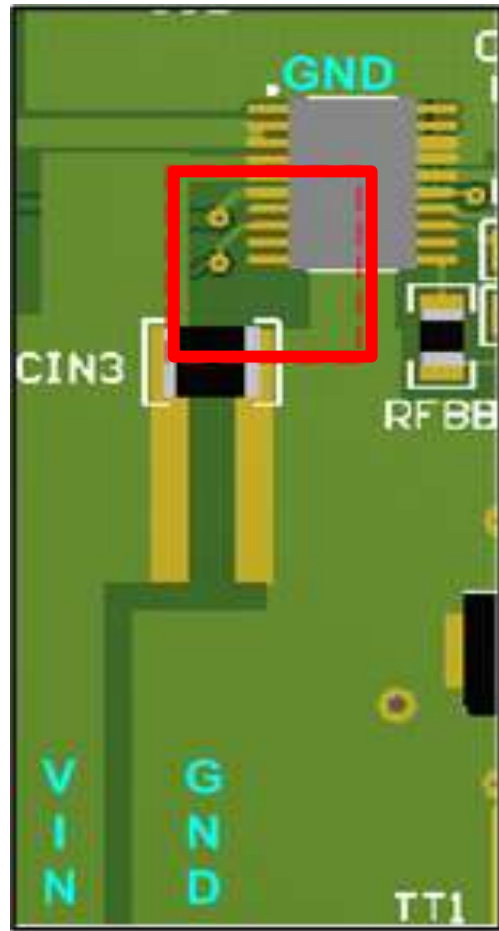


# HF noise reduction – component placement

- For a Buck converter...
  - The **INPUT cap** position affects the **OUTPUT noise!**
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# High di/dt capacitor placement - example

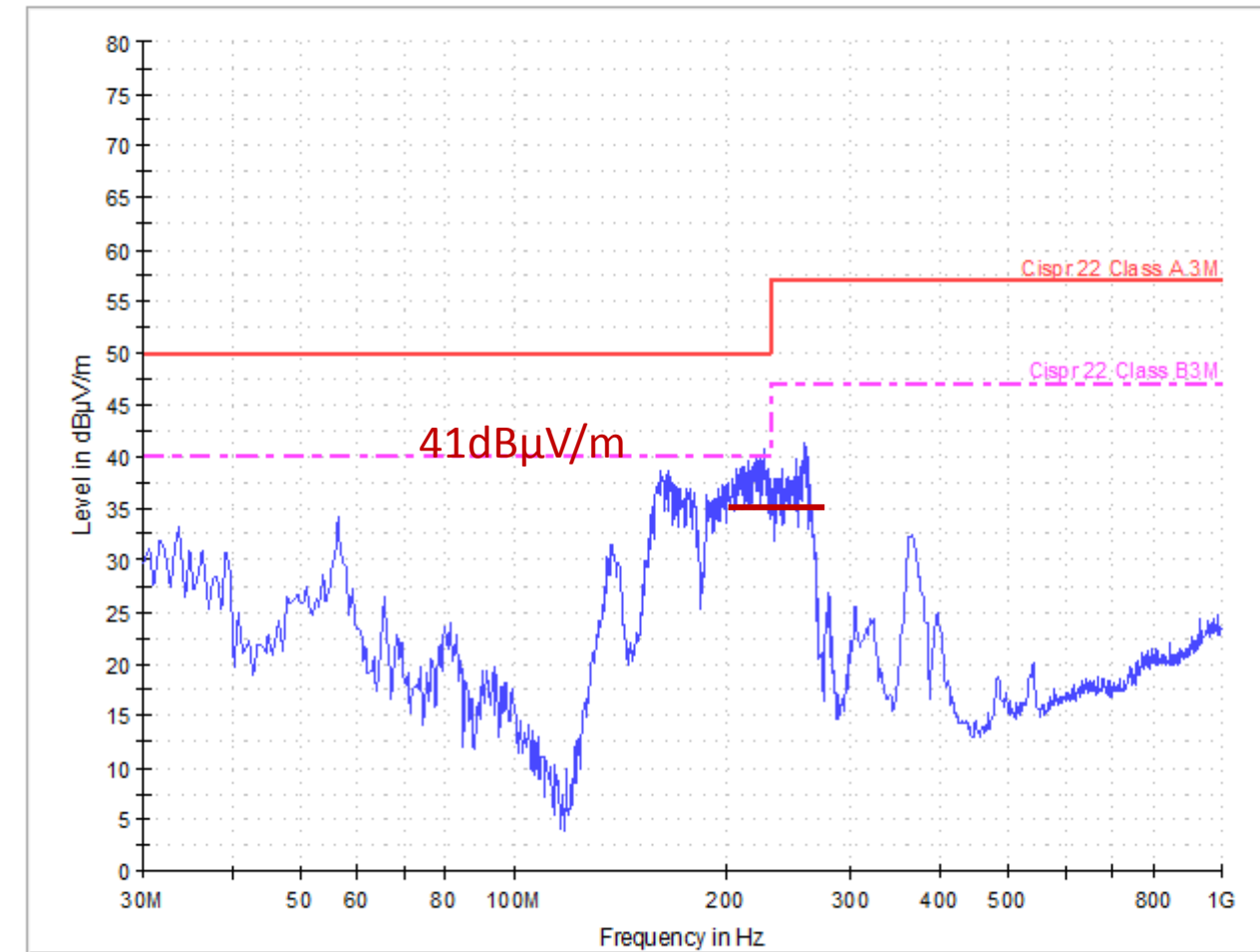
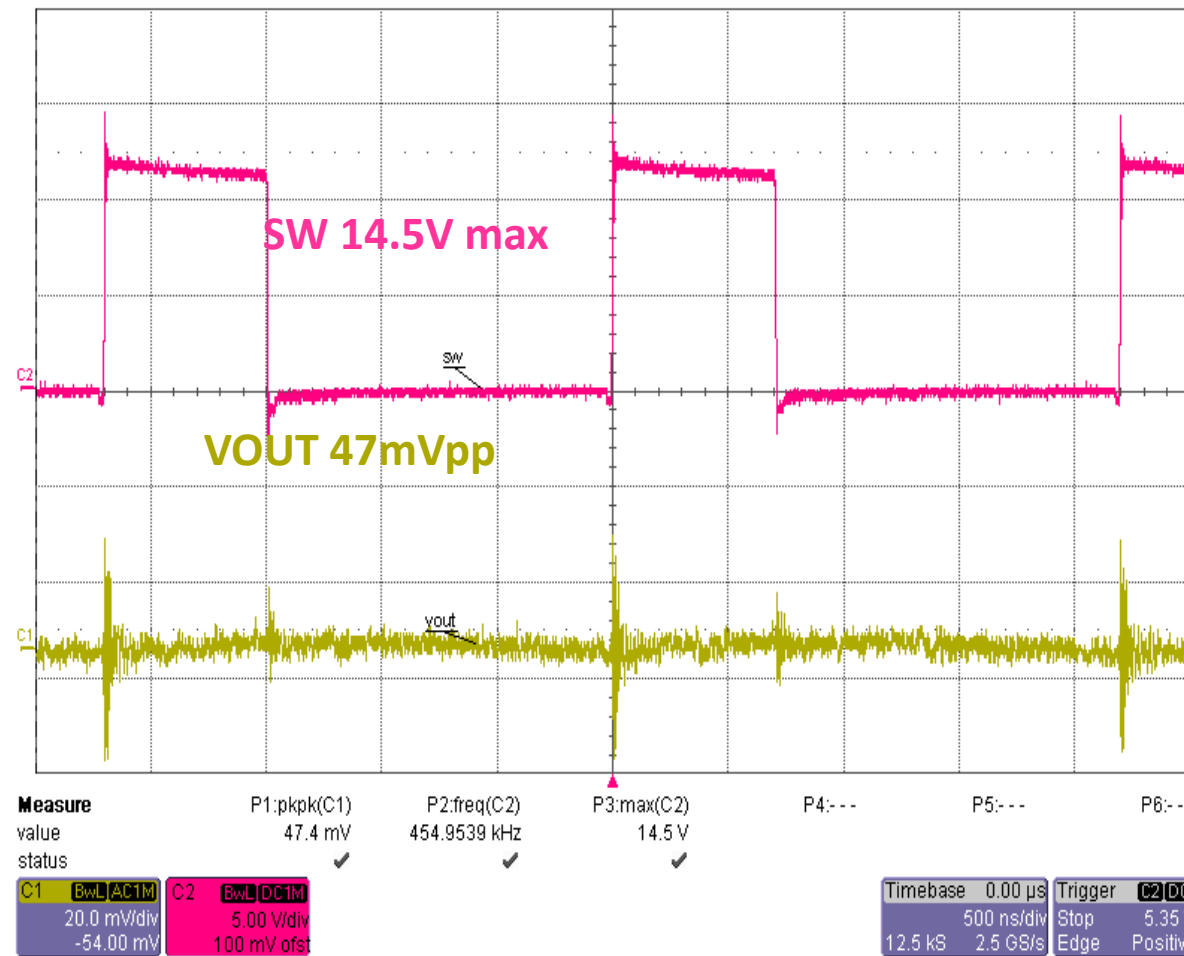
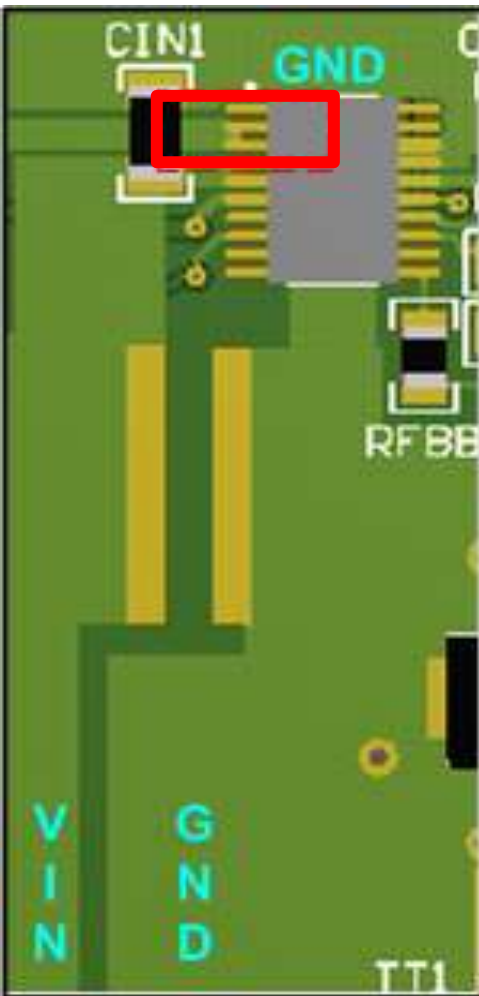
- Buck Regulator comparison with Cin location
- 12V input, 3.3V output, 2A Buck



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# High di/dt capacitor placement - example

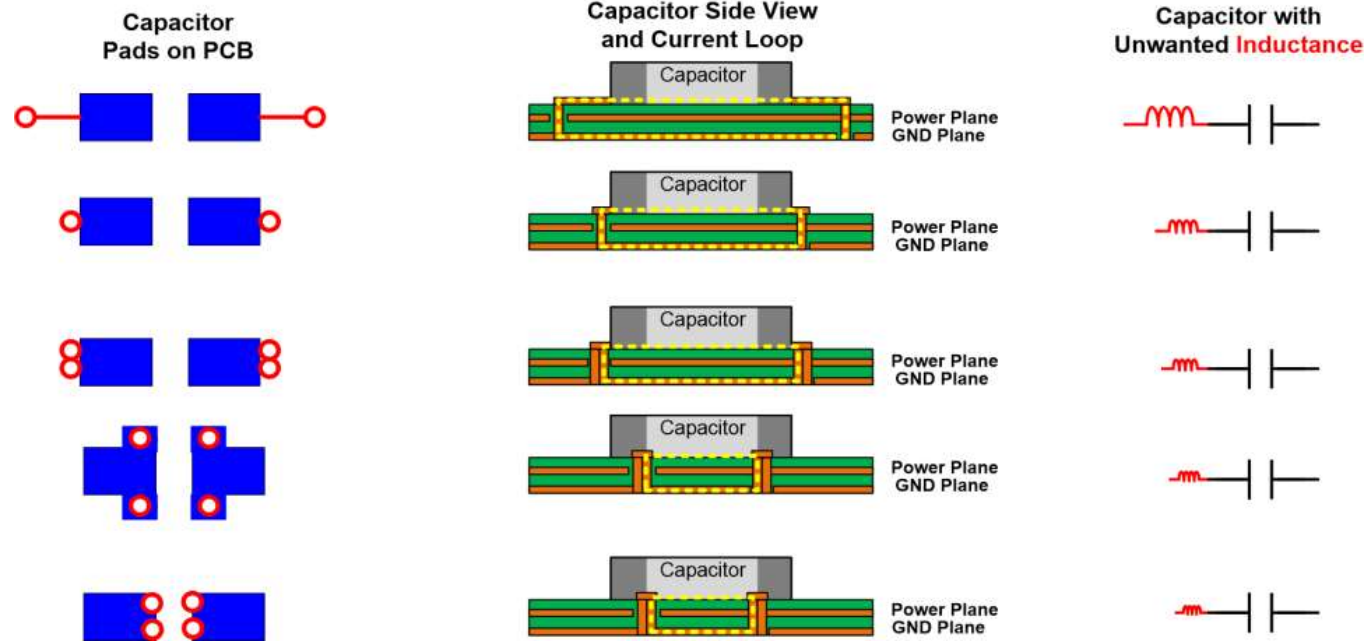
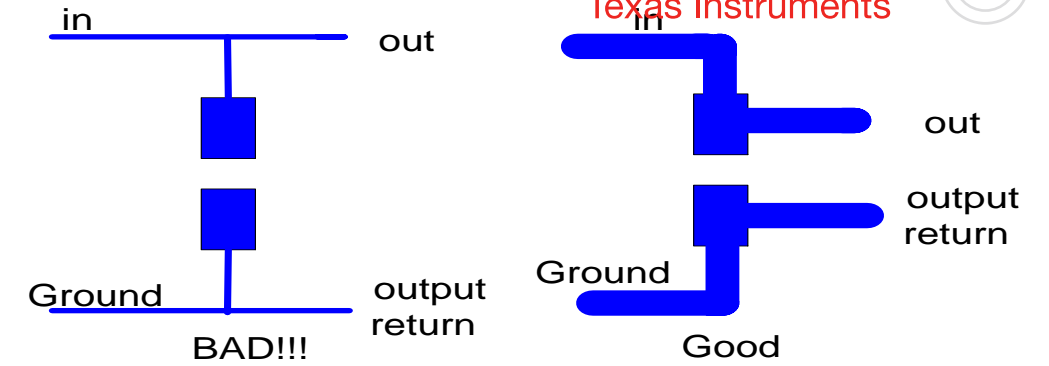
- Buck Regulator comparison with Cin location (2 times smaller loop area)
- 12V input, 3.3V output, 2A Buck



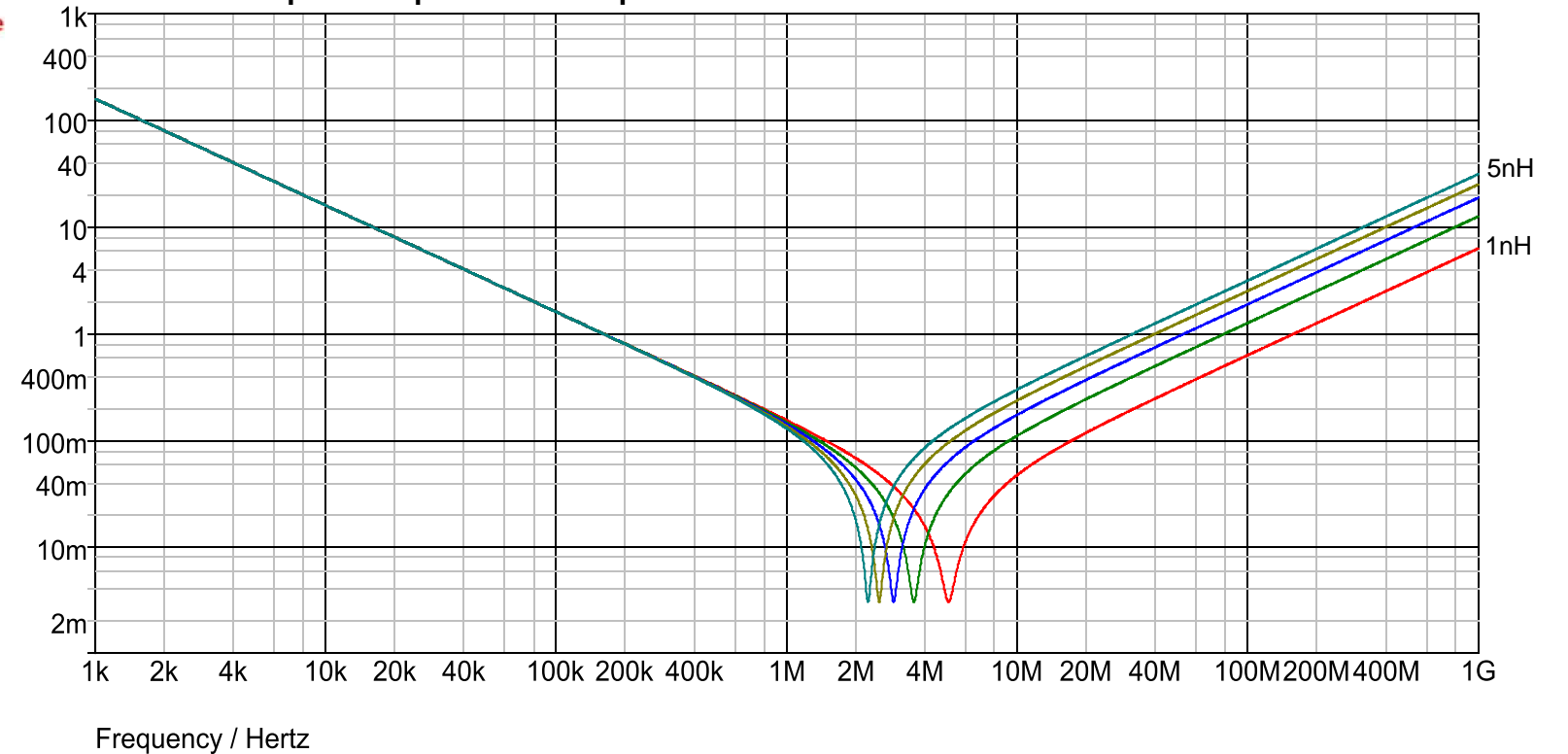
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# Bypass capacitor routing - example

- Place bypass capacitors on same side of board as component being decoupled
- Locate as close to pin as possible
- Keep trace width thick and short

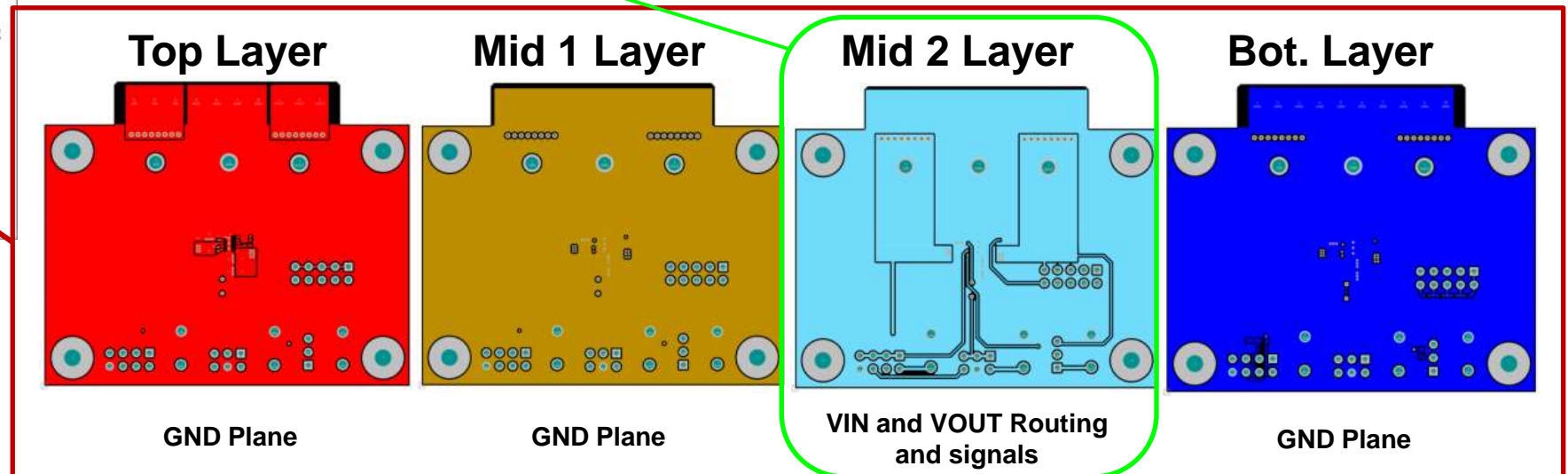
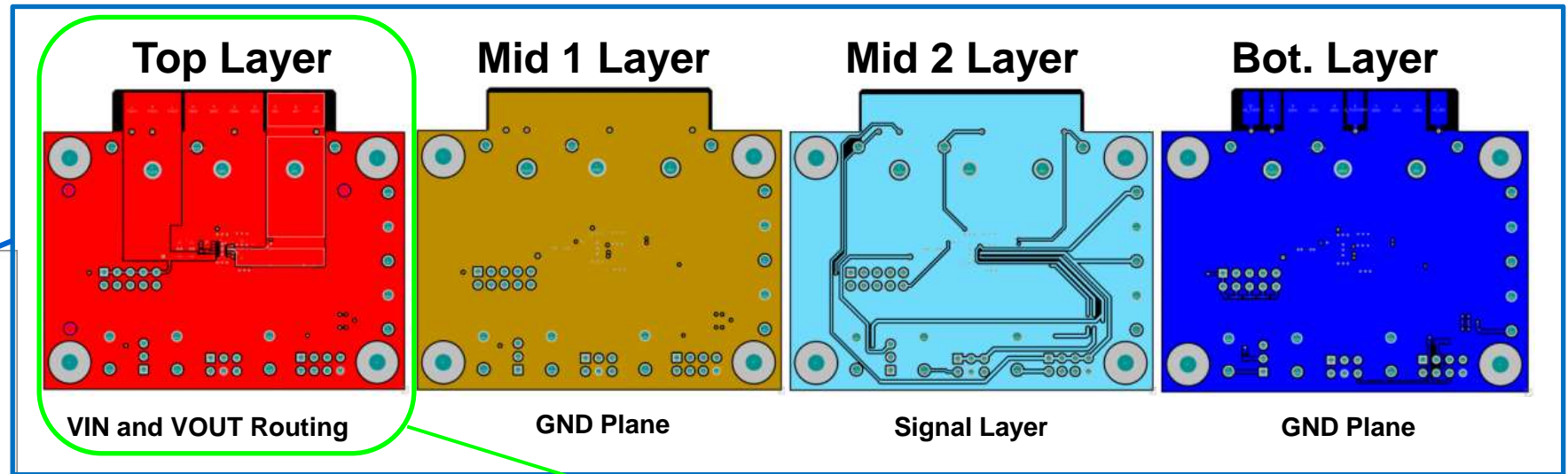
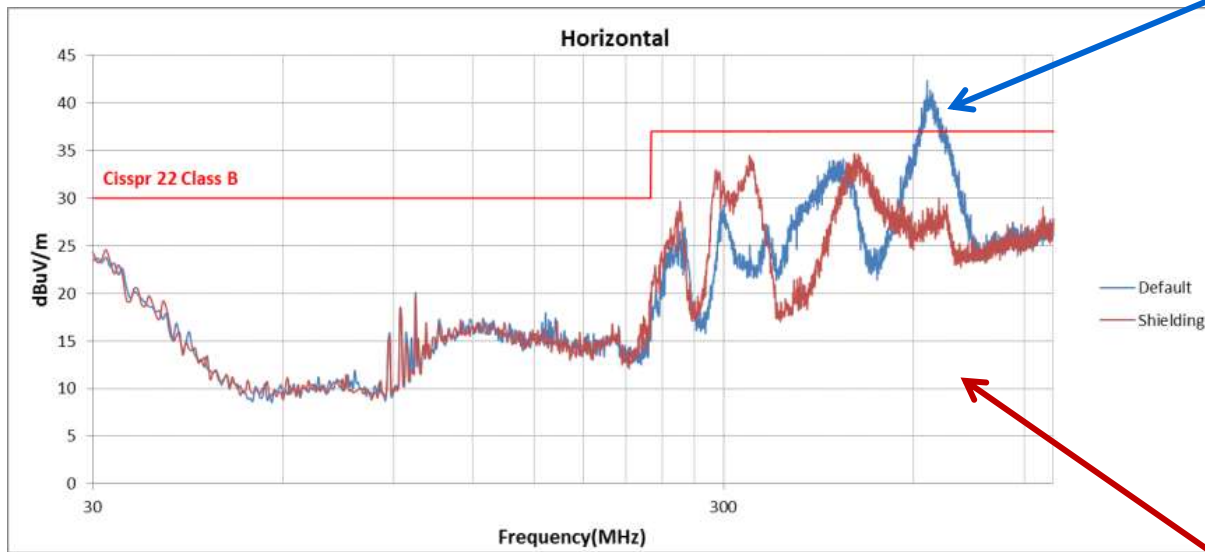


1 $\mu$ F Capacitor Impedance With Various ESL



# HF noise reduction – board layout tricks

## Shielding

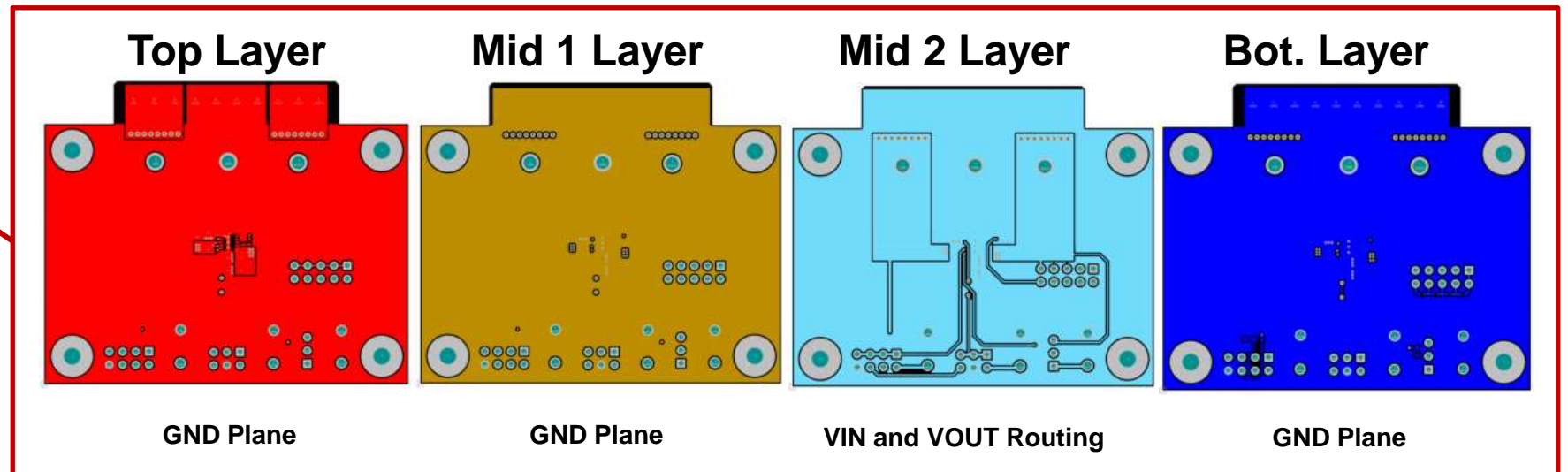
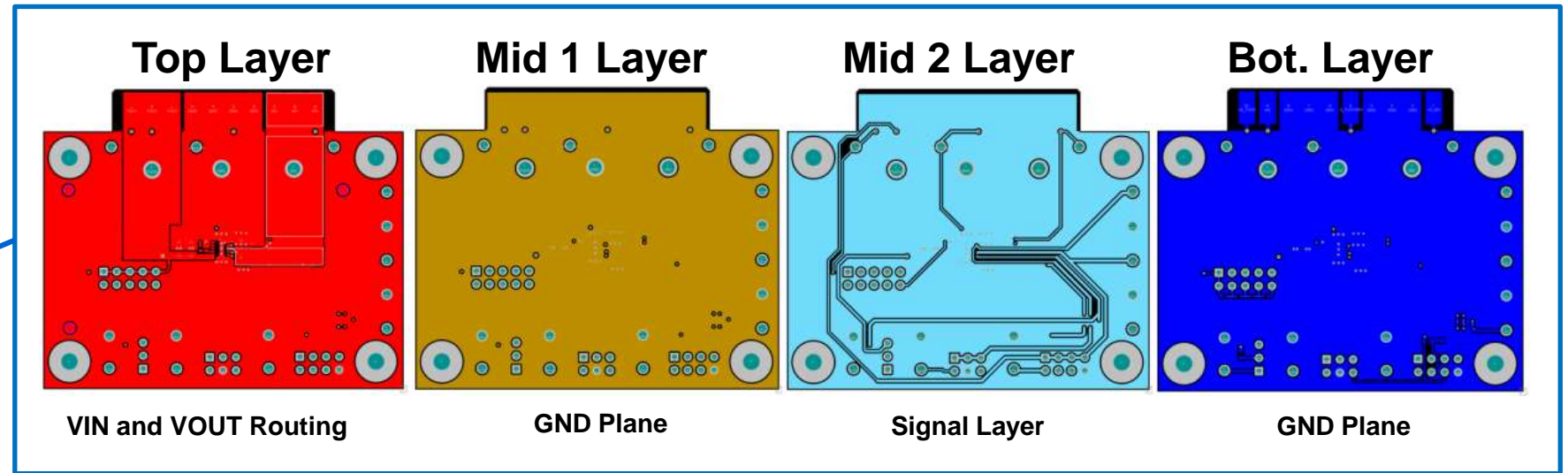
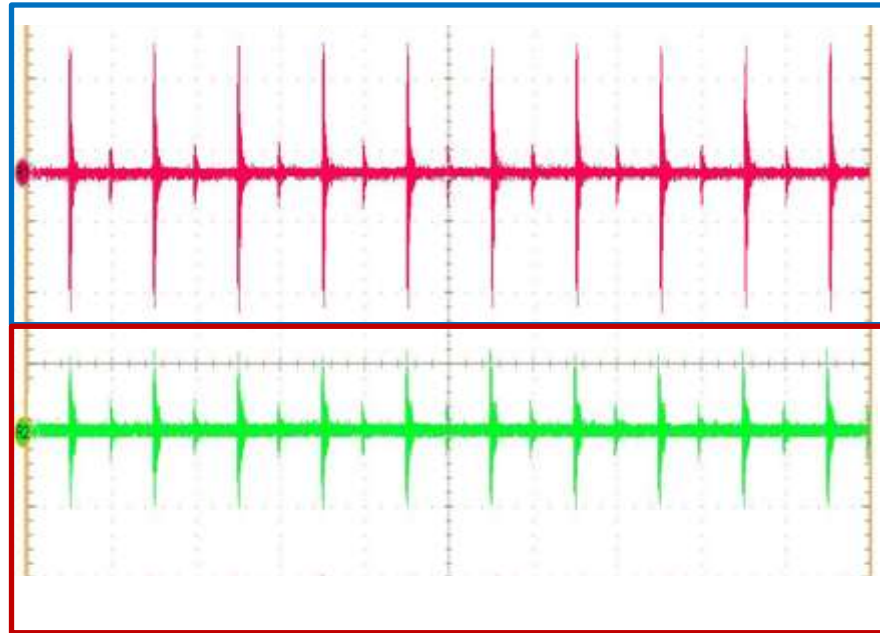


- Same BOM!
- Different stackup
  - Shielding the input (noisy) and output lines
  - Fail by ~5dB vs Pass by ~2dB

Understanding → Measuring → Reducing Noise

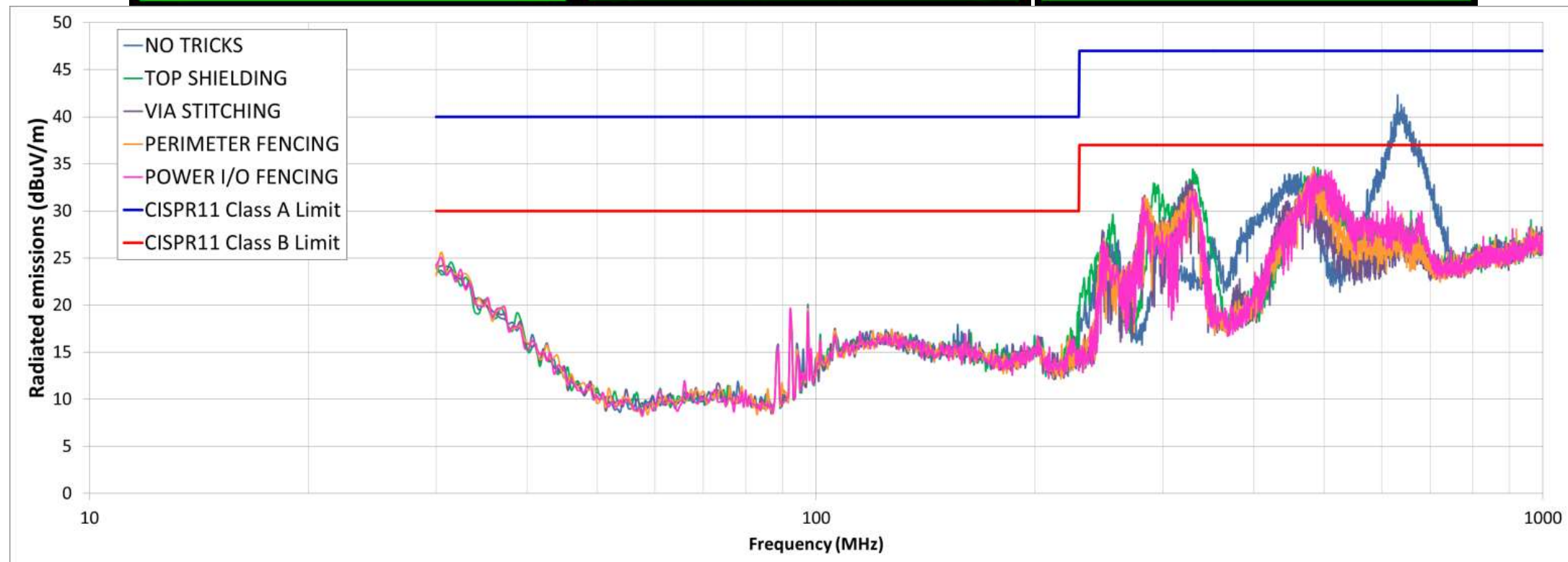
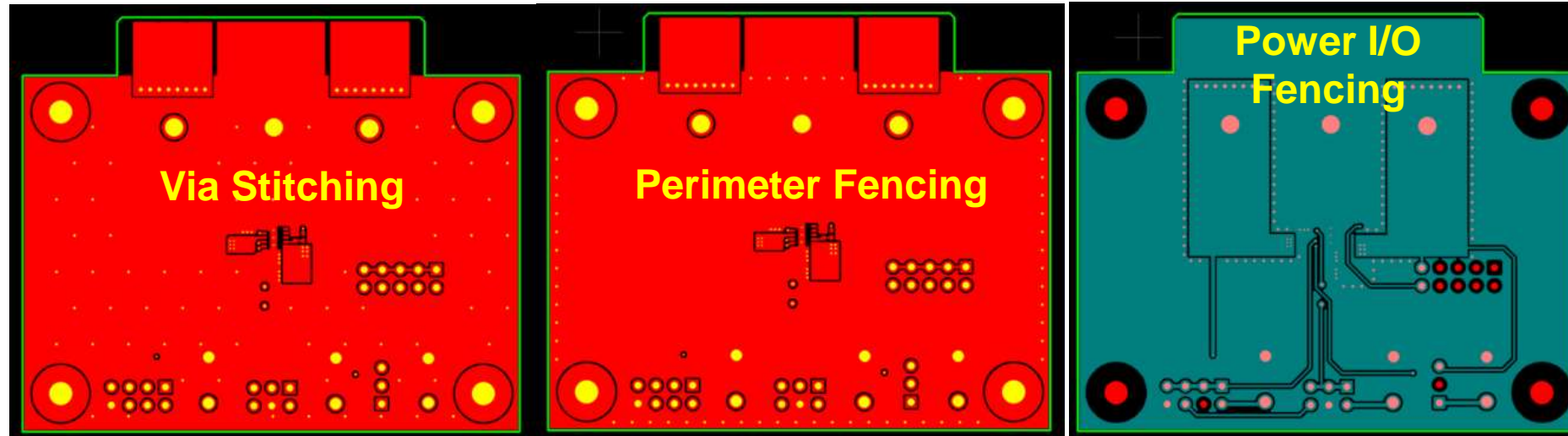
# HF noise reduction – board layout tricks

Shielding

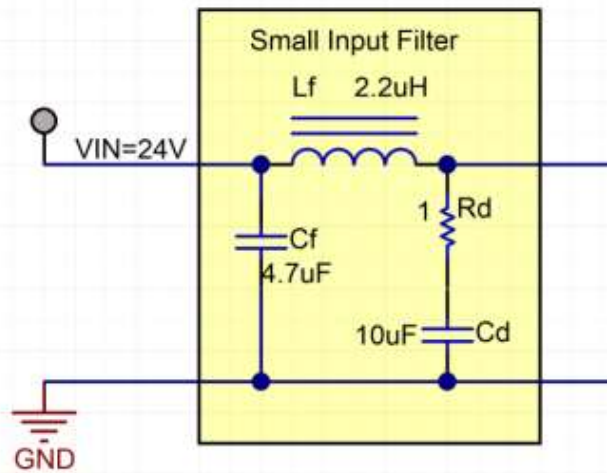


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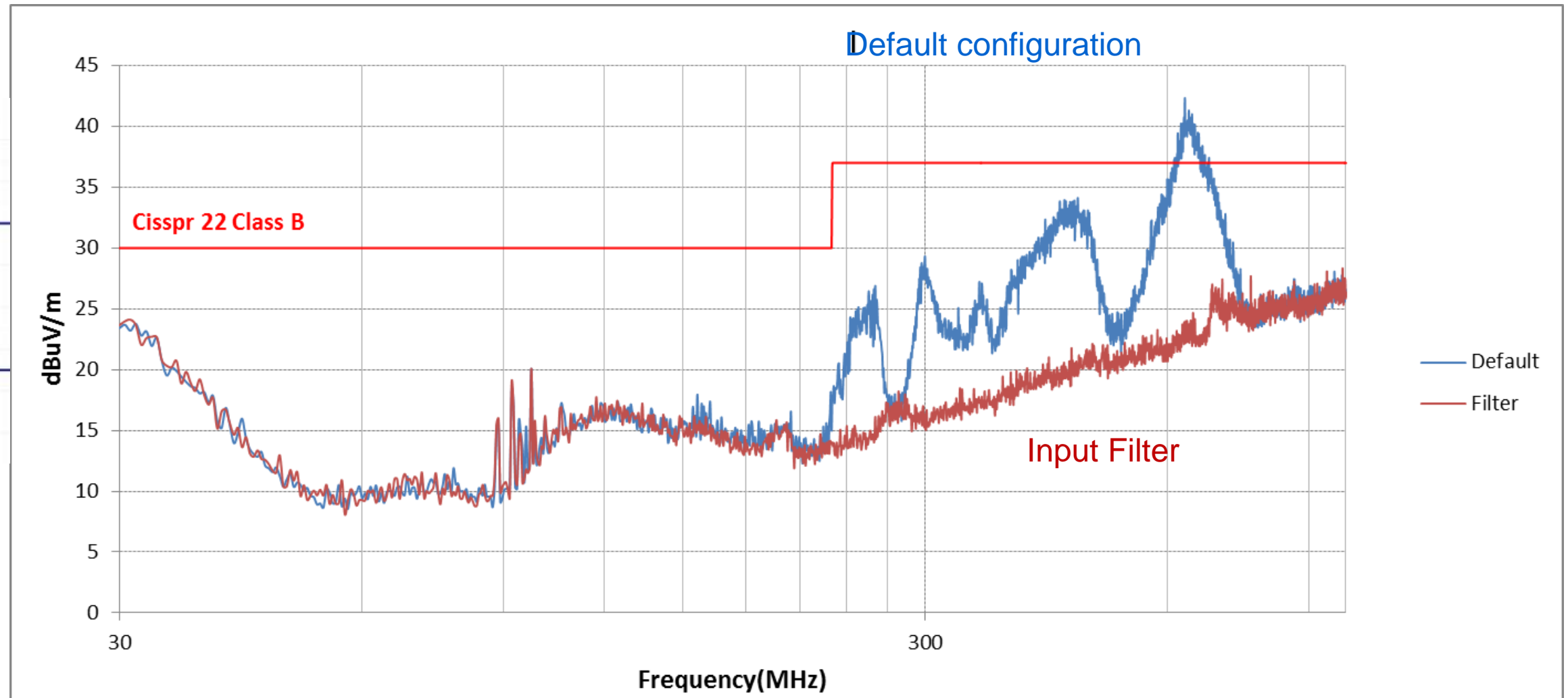
# HF noise reduction – board layout tricks



# Conducted EMI filter and radiated EMI performance



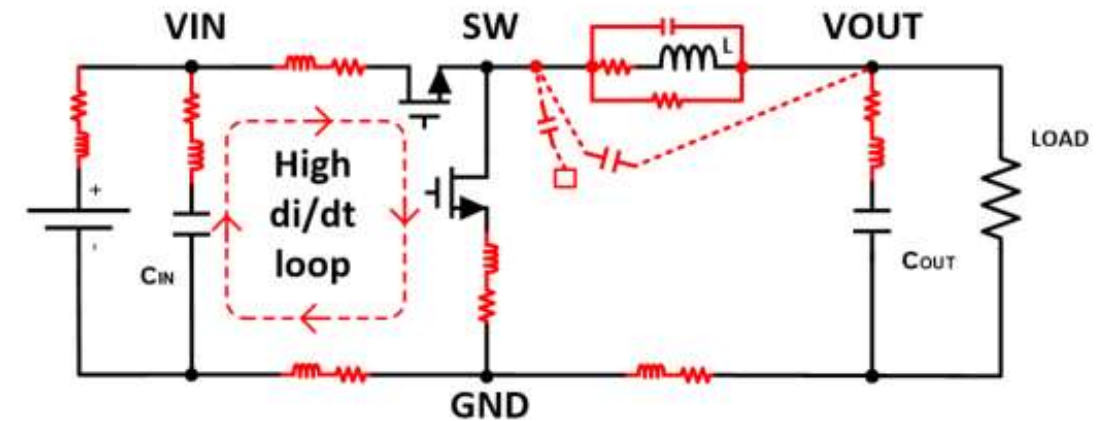
Calculator





# HF noise reduction – package level parasitics

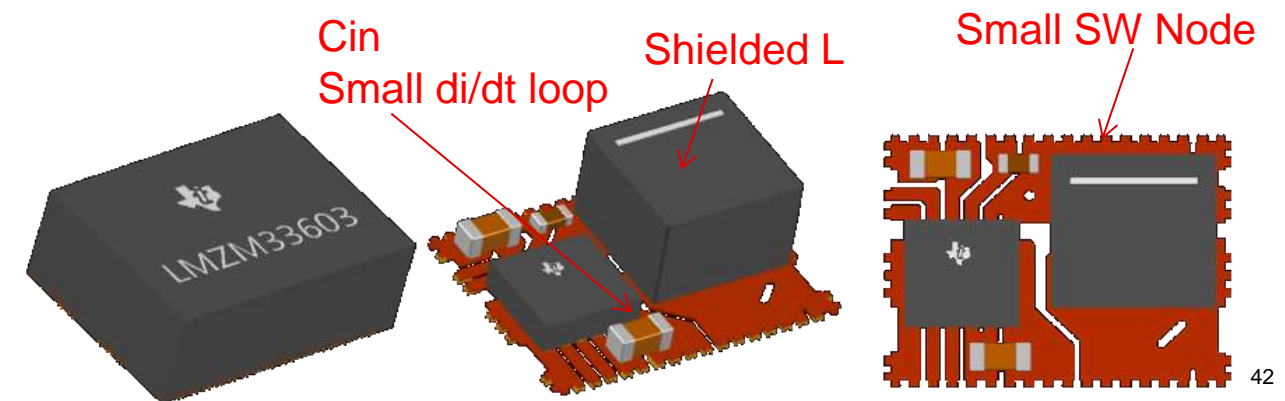
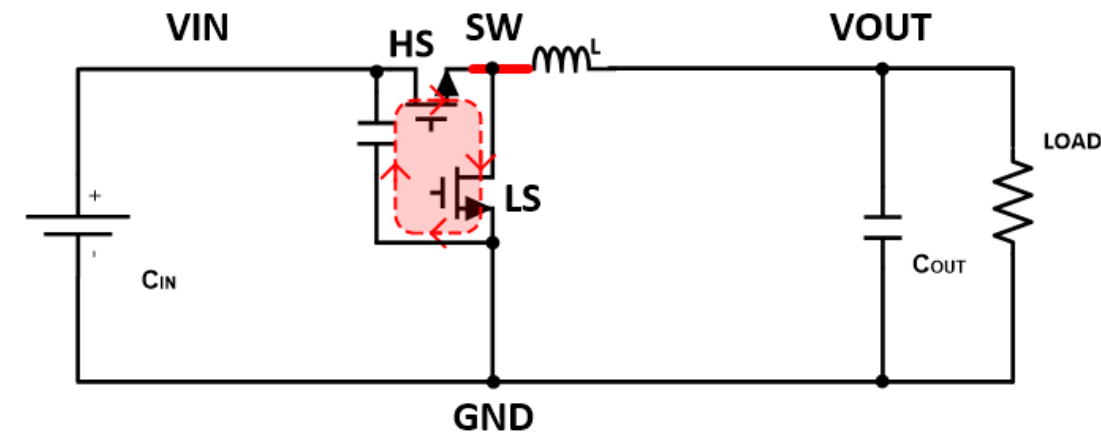
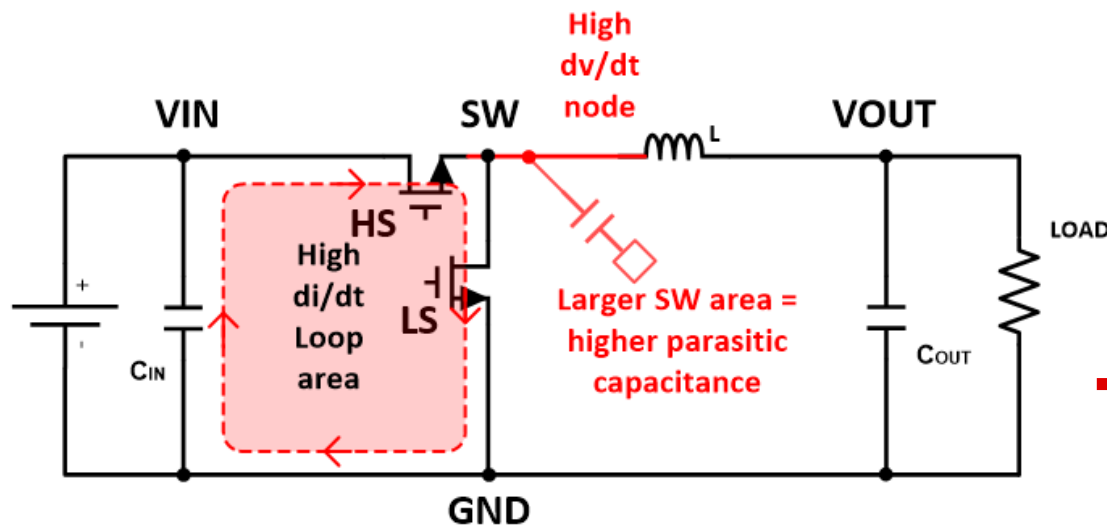
- Some packaging options are better for reducing inductance in the high di/dt loop.
- Power module packages can integrate a high frequency bypass capacitor.
- IC Pinout and Construction Matters



# HF noise reduction – DC-DC power modules save you layout troubles

- Reducing the high di/dt loop area – integrated input capacitance.
- Reducing the high dv/dt node area – integrated L and smaller switch node.

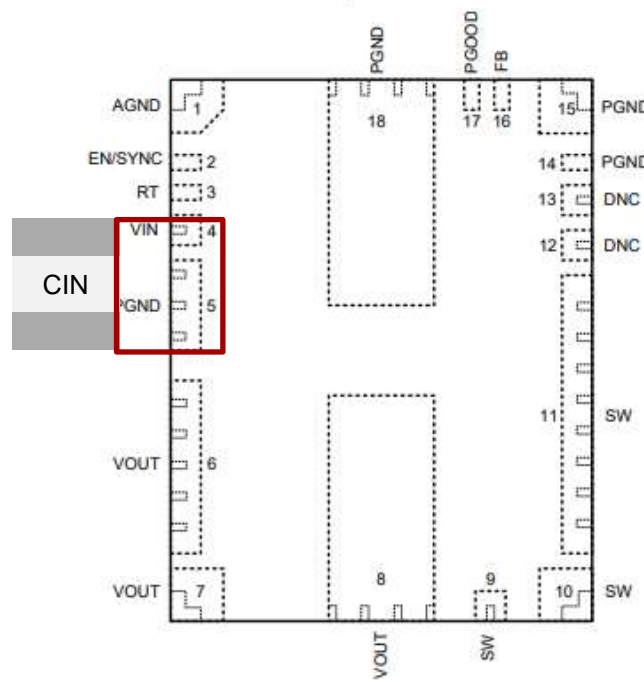
Discrete solution without optimized layout → DC-DC Power Module



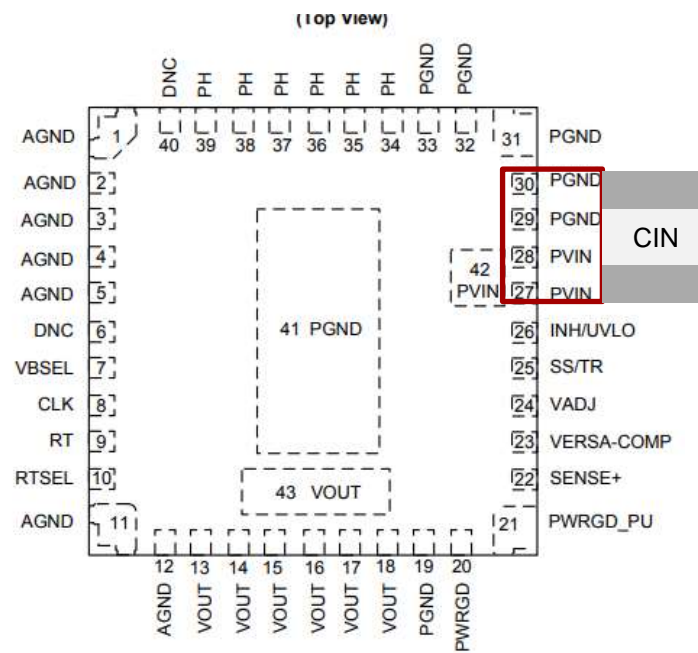
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# HF noise reduction – proper pinout

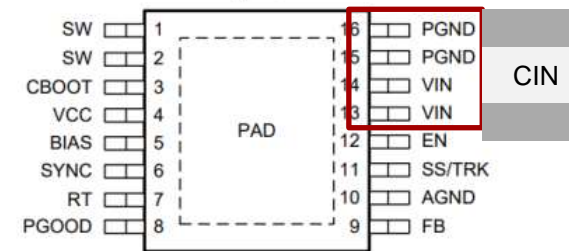
- To minimize the di/dt loop, it is best if the Buck regulator has VIN and PGND pins next to each other. This allow for placing the input capacitor as close as possible to the IC.



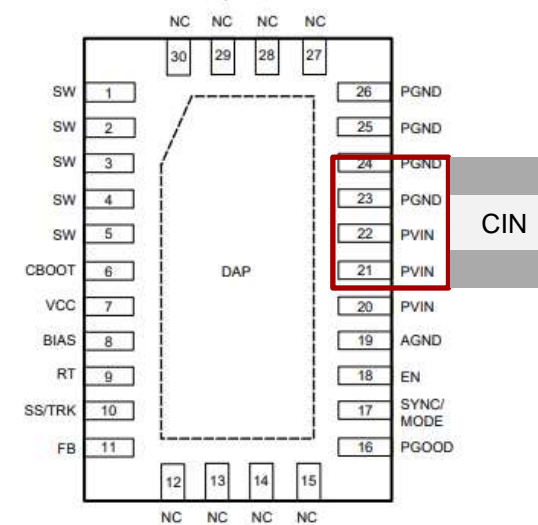
LMZM33603



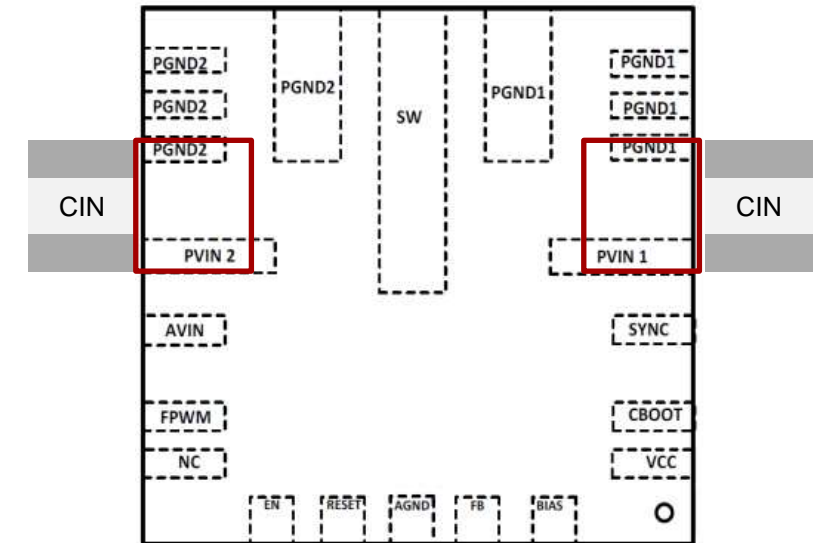
LMZ36002



LM46002



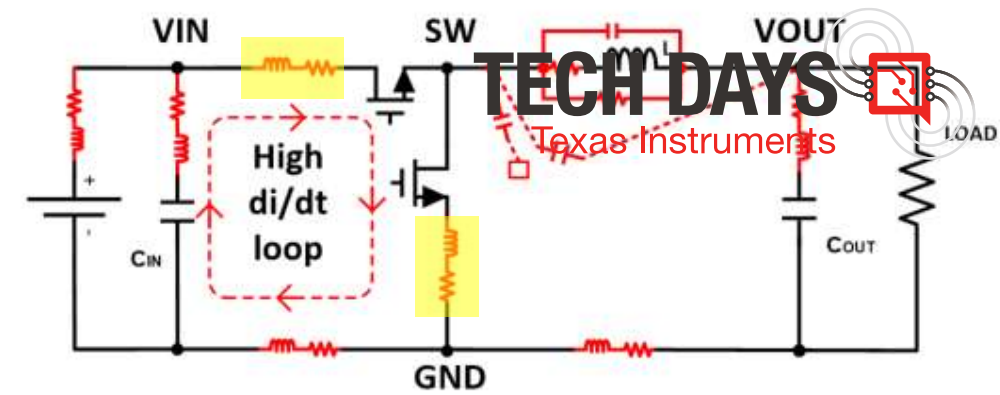
LM73606



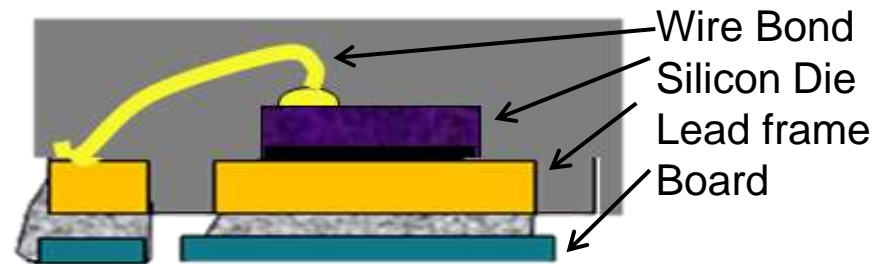
LMS3635

# IC package construction can help

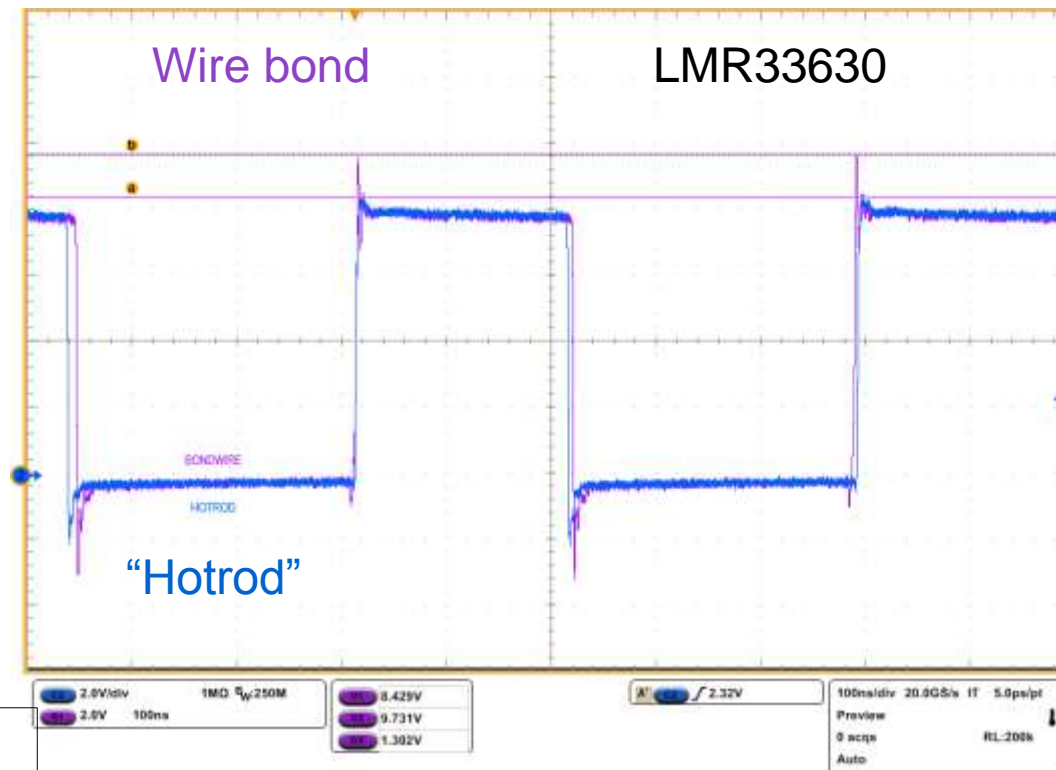
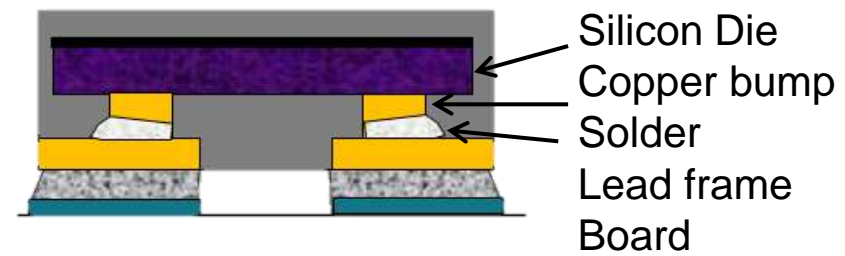
- Bond wire vs Copper pillar interconnects



Standard wire bond QFN package



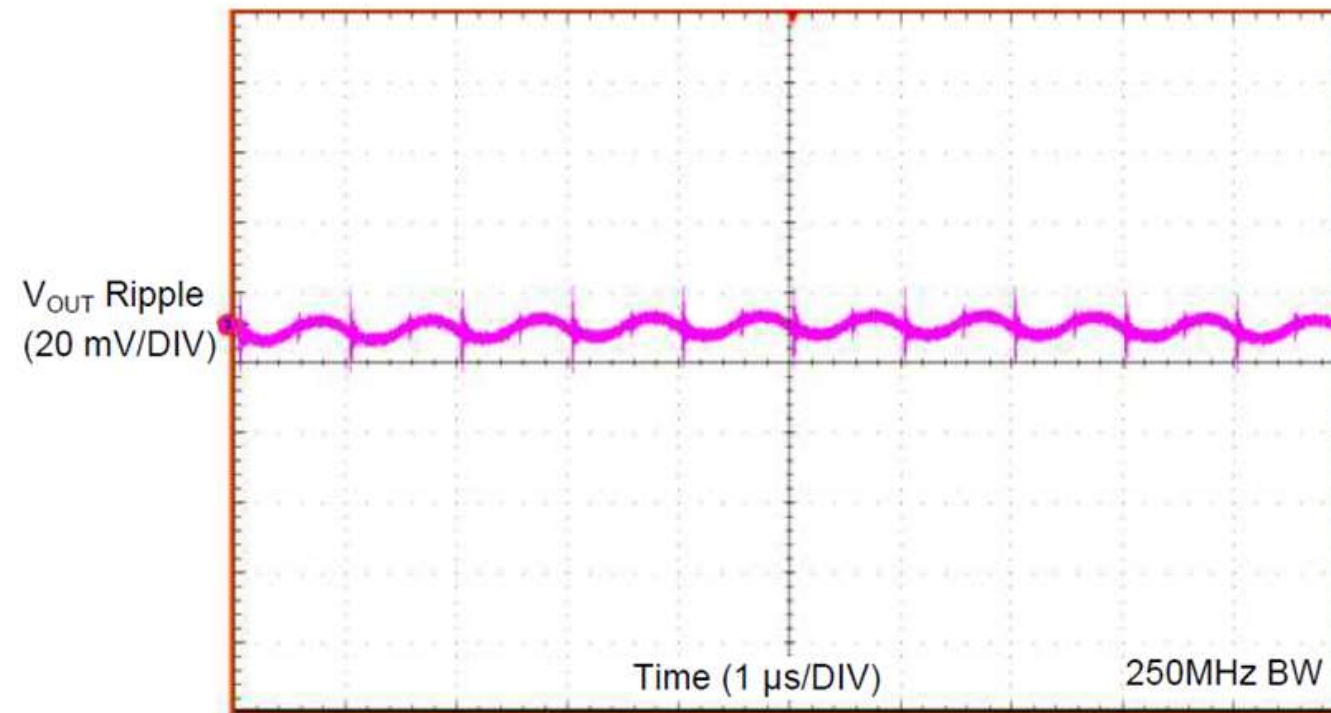
'Hotrod' flip chip on lead frame QFN



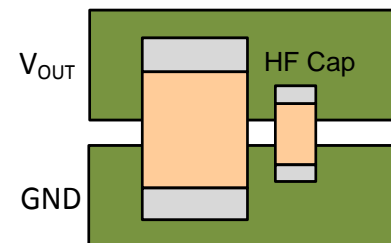
Understanding → Measuring → Reducing Noise

# HF filtering

- After careful input capacitor placement and layout there will be some left over high frequency noise – we cannot completely eliminate parasitic L and C.

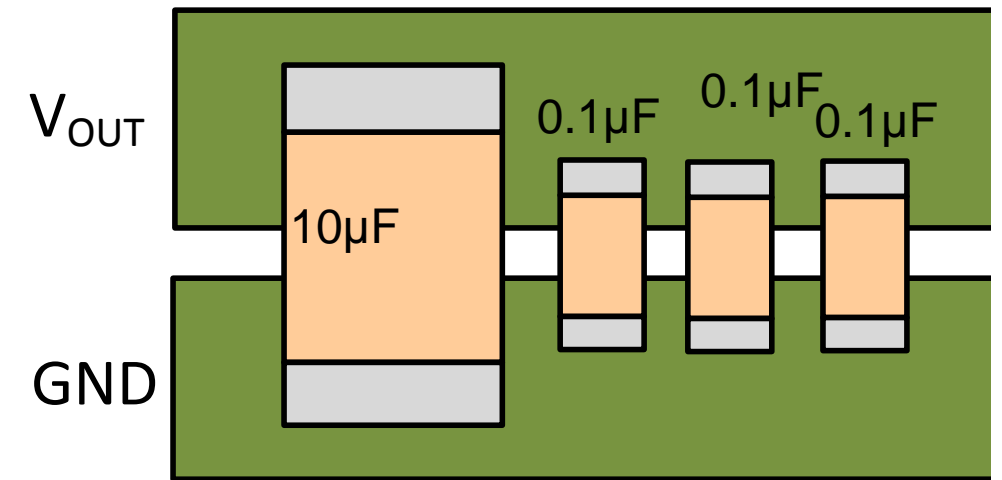
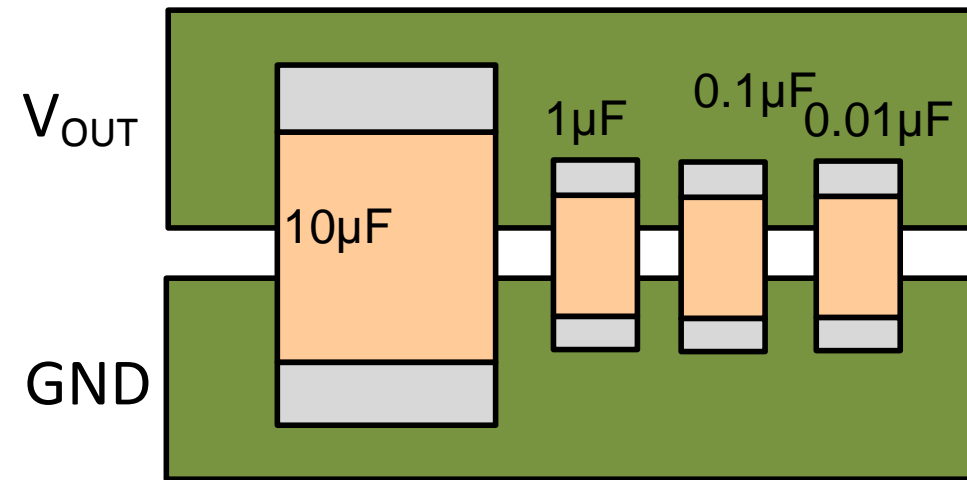
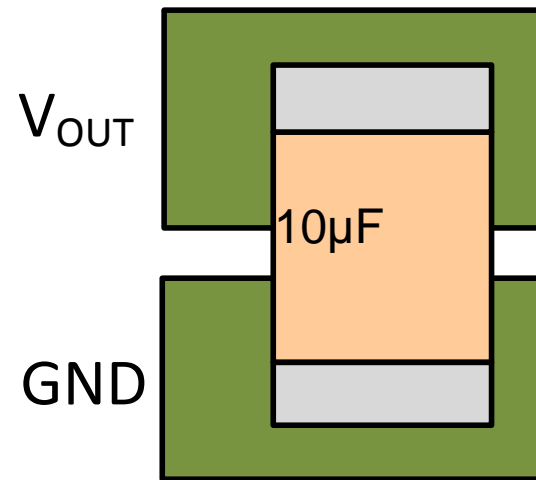


- How can we reduce it?



# HF filtering

- Which one is better?

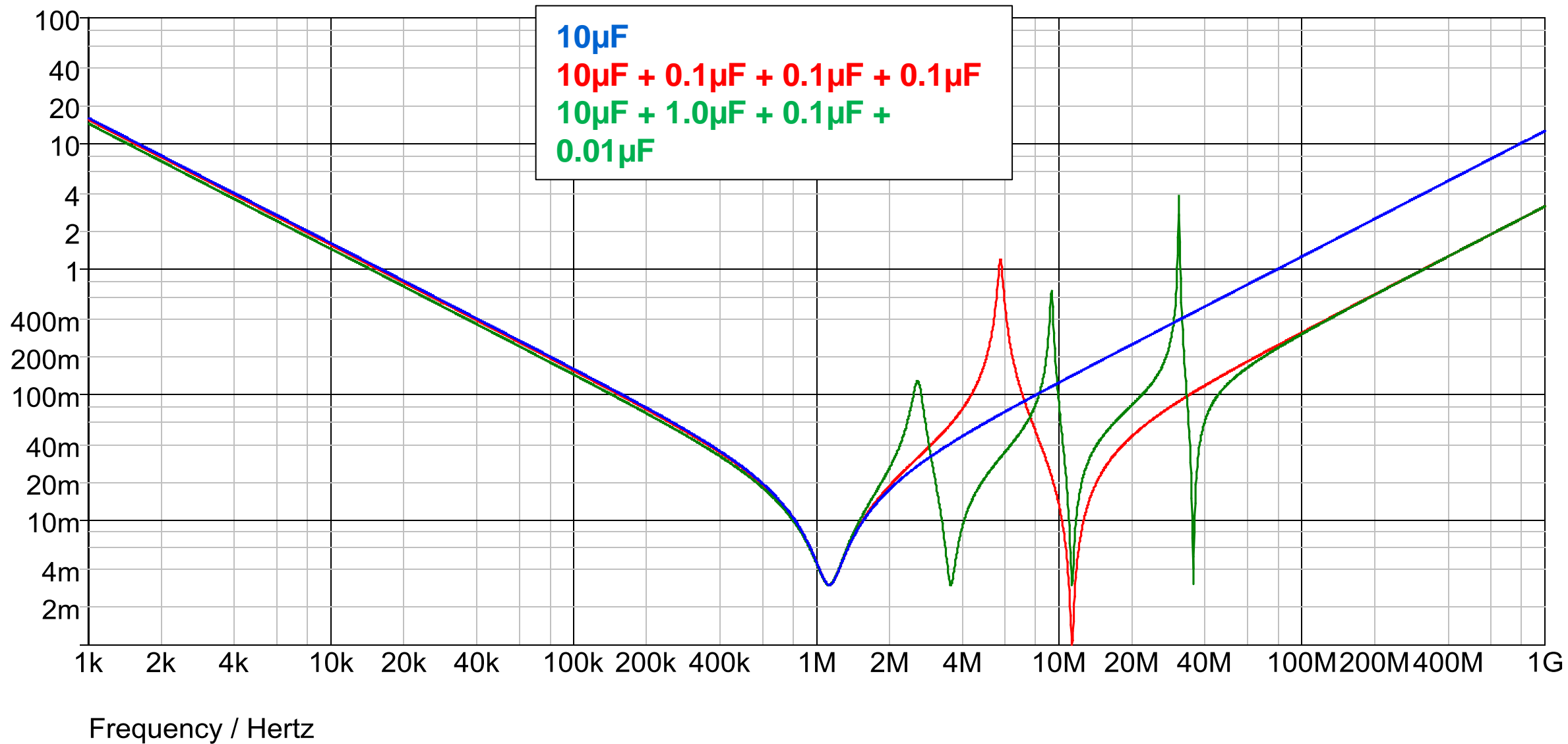


# HF filtering

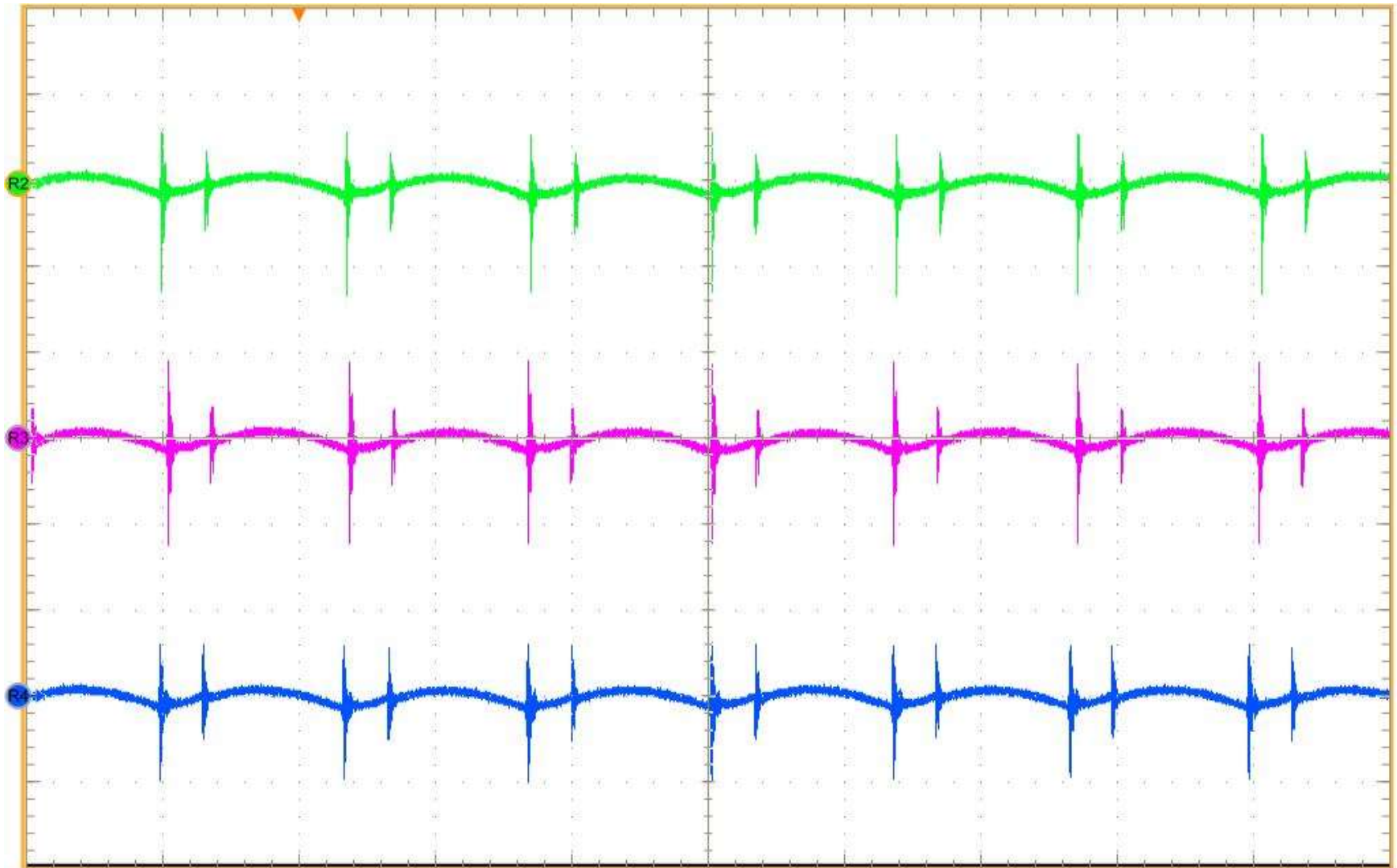
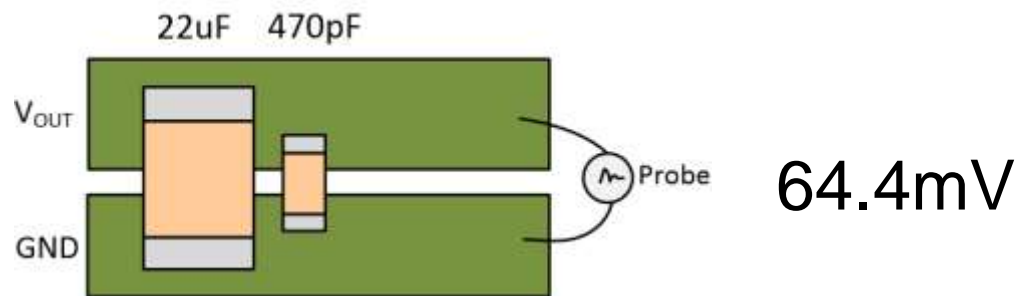
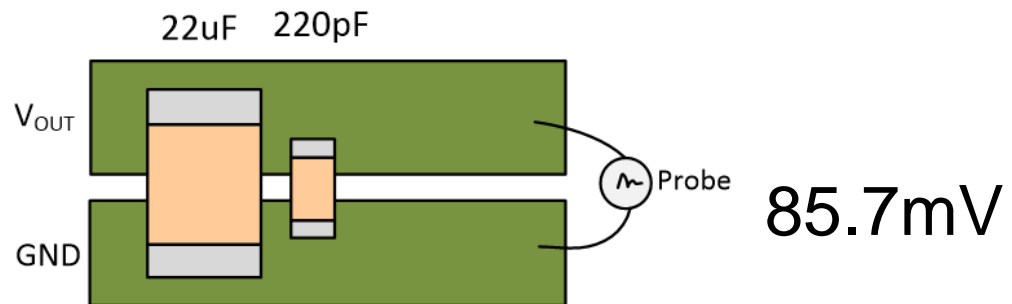
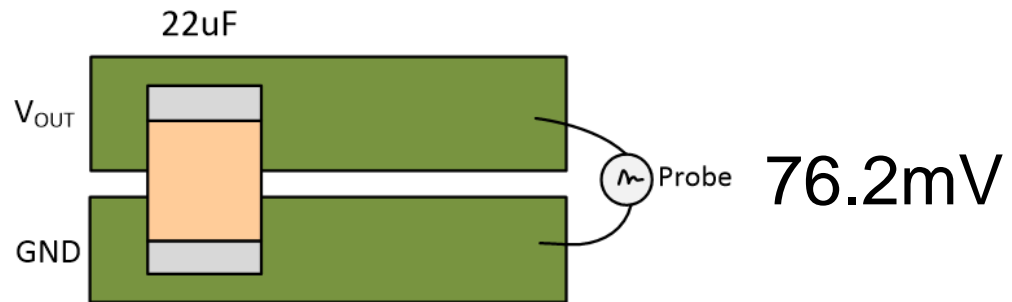
SIMetrix schematic example:



parallel\_capacitor\_impedance.sxsch



# HF filtering with wrong capacitor (example)



R2 40.0mV 1.0µs  
R3 40.0mV 1.0µs  
R4 40.0mV 1.0µs

A C1 2.8mV

1.0µs/div 10.0GS/s 100ps/pt

Run Sample

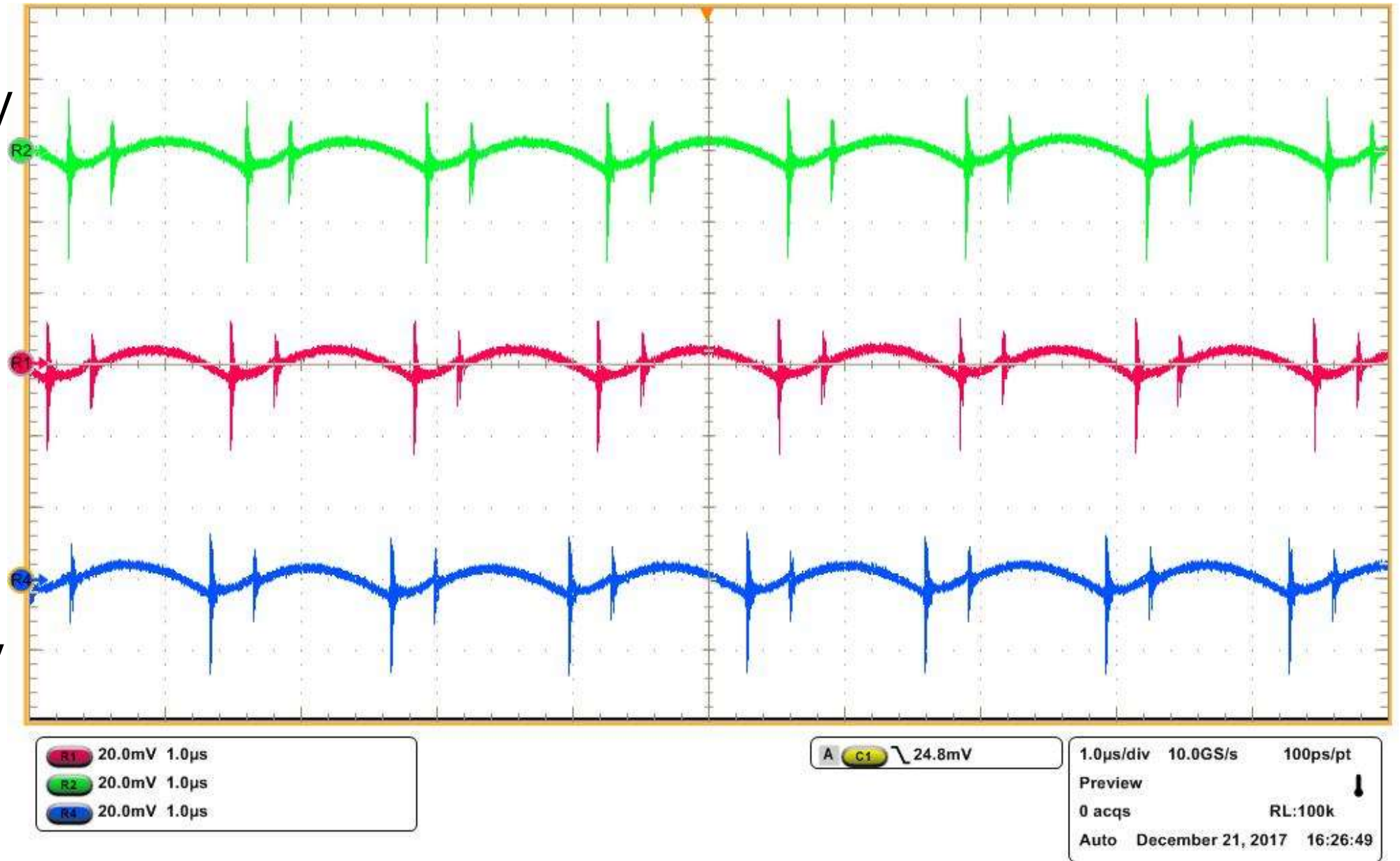
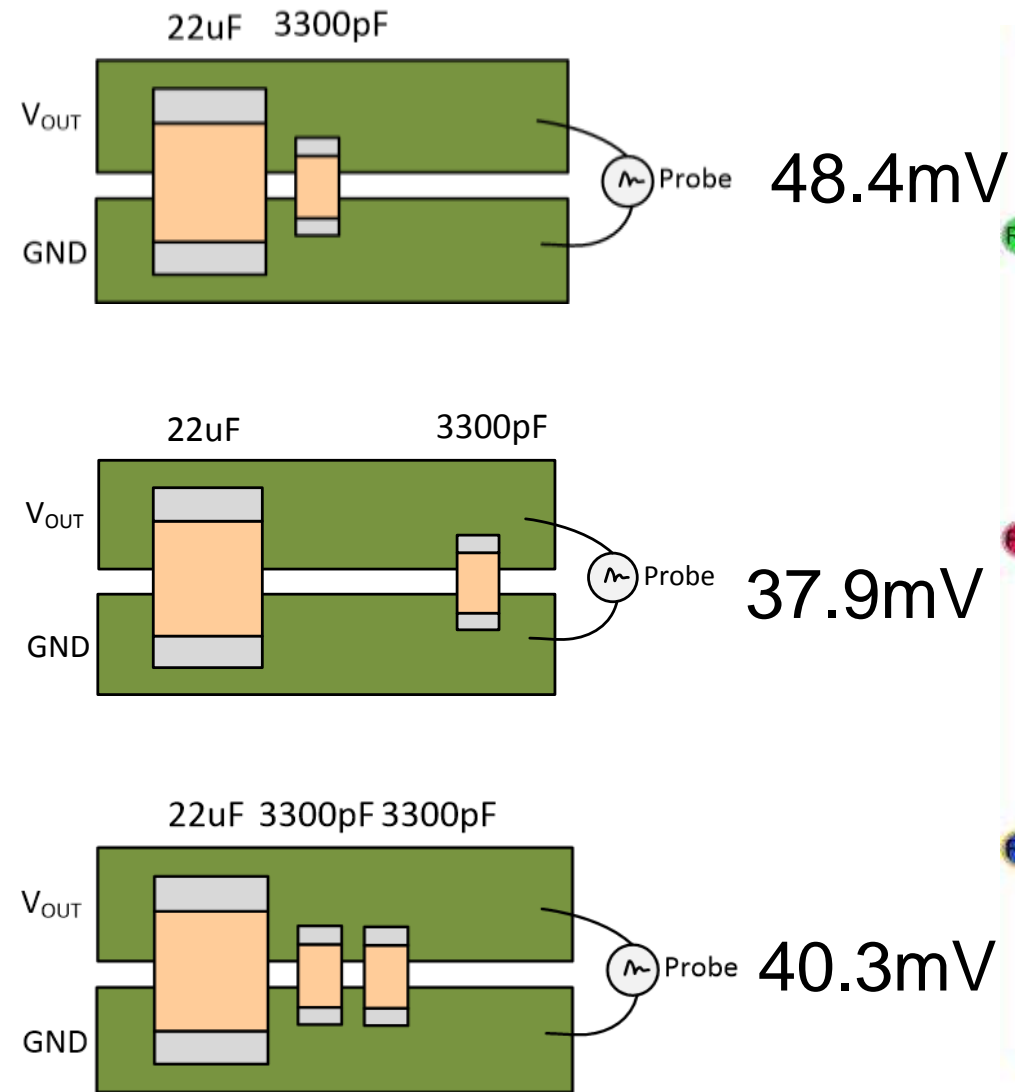
0 acqs RL:100k

Auto December 21, 2017 15:42:14

Understanding → Measuring → Reducing Noise



# HF filtering - utilizing PCB parasitic inductance



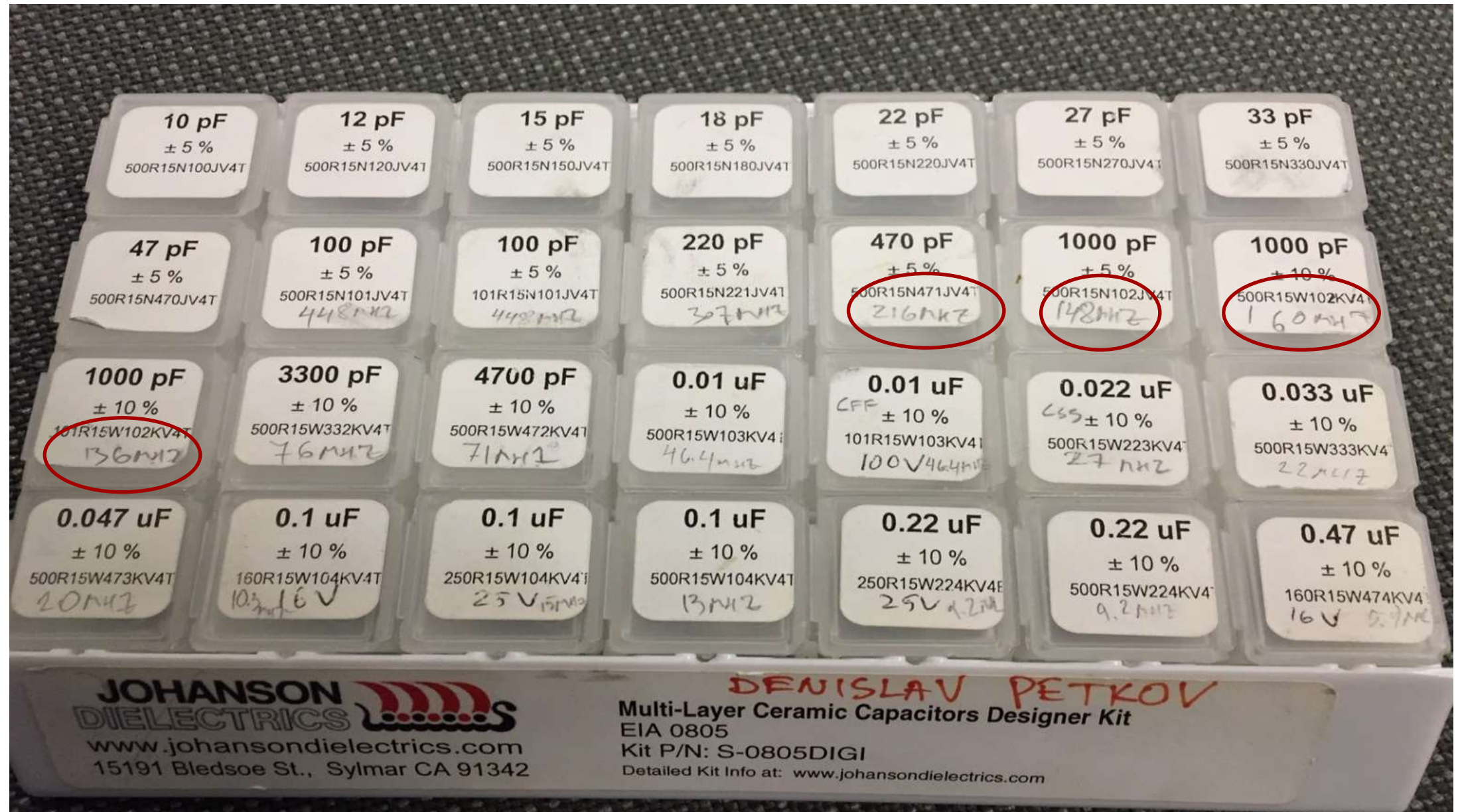
Understanding → Measuring → Reducing Noise

# HF filtering – strategy

- Leave footprint in the layout for 2-3 HF filter capacitors.
- Measure the ringing frequency and pick a capacitor with an impedance notch close to, but lower than that frequency.
- Use multiple capacitors of the same value in parallel to avoid new peaks in the impedance curve.

# HF filtering – pick the correct capacitor

- Measure your caps
- Mark up your capacitor kit!
- This data may also be available from the capacitor vendor.



# Summary

- Understanding the Noise Sources
- Measuring Noise
- Reducing Noise (high frequency and low frequency)

- **Application Notes and Blogs on EMI and Noise Reduction**
  - [Simple Success With Conducted EMI From DCDC Converters](#)
  - [Simplify low EMI design with power modules](#)
  - [Wiki on Understanding, measuring, and reducing output voltage ripple](#)
  - [Design a second-stage filter for noise sensitive applications](#)
  - PCB layout techniques for low noise power designs (in progress)



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